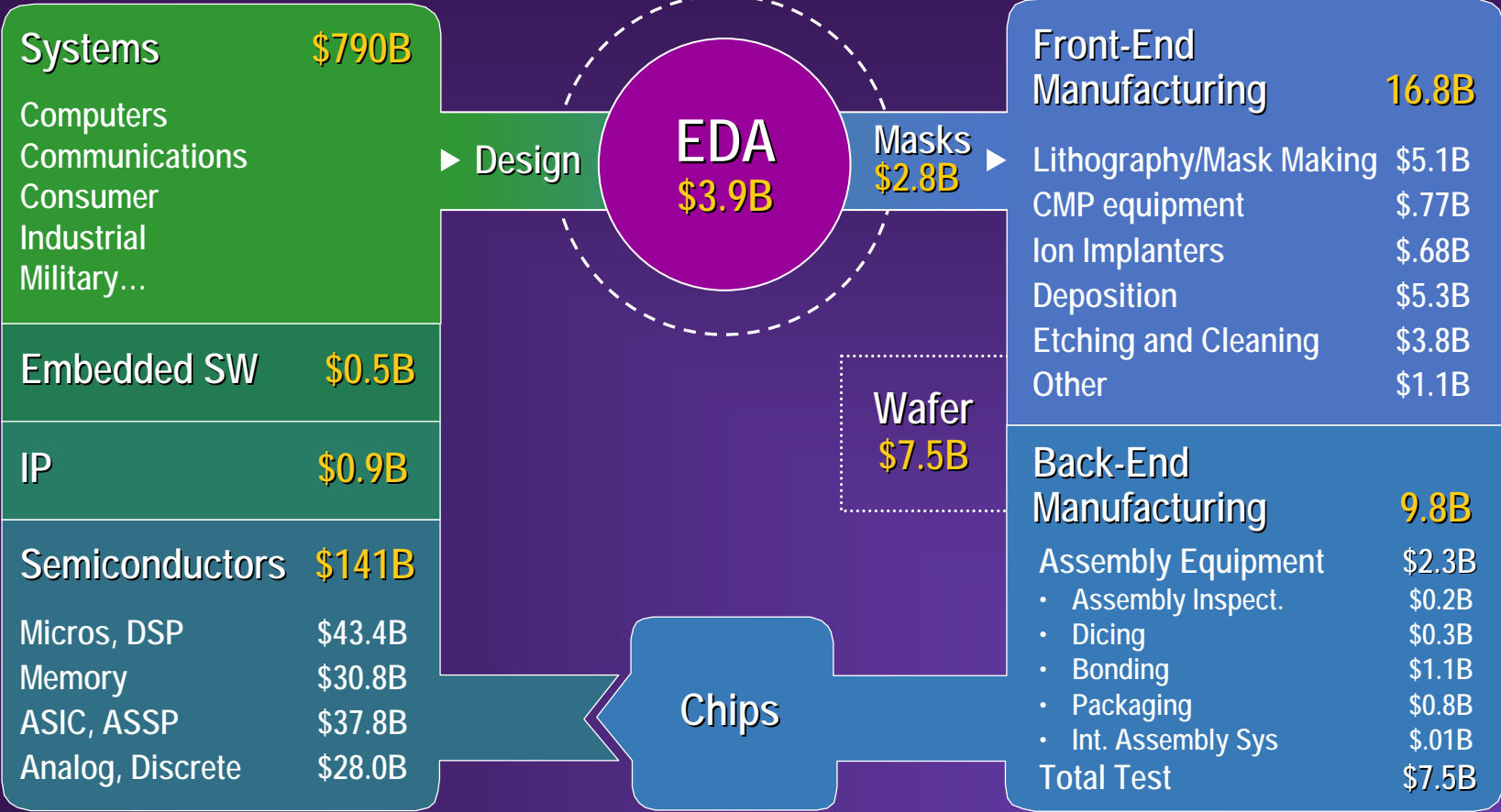


65nm: Business As Usual?

Dr. Raul Camposano
Senior Vice President,
Chief Technology Officer
Synopsys, Inc.



Semiconductor Process Flow



Technology Roadmap



Smaller, Cheaper

Increasing Design Cost

Faster

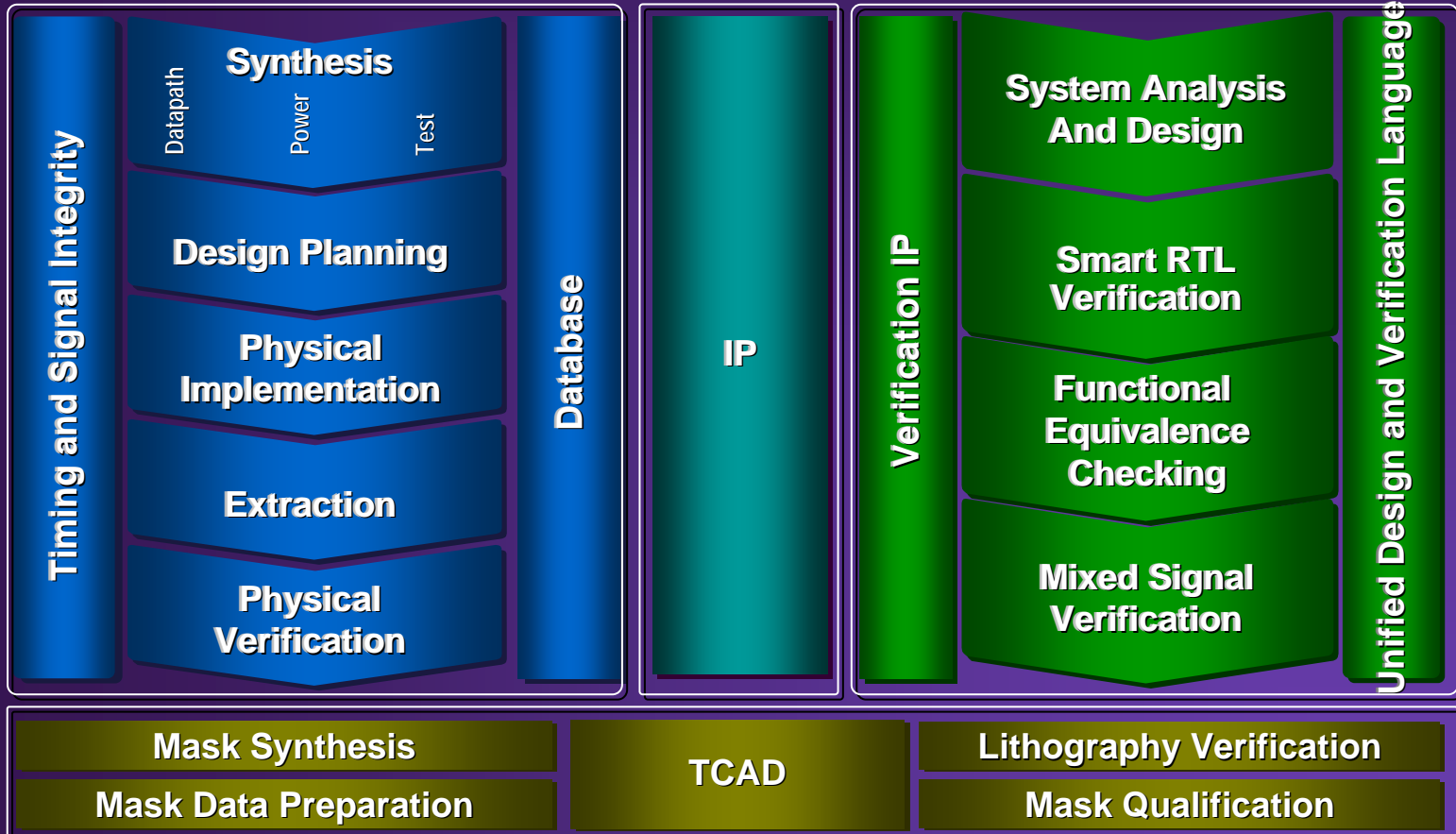
Less Power

Parasitics
CD Variability

Leakage
Power Density

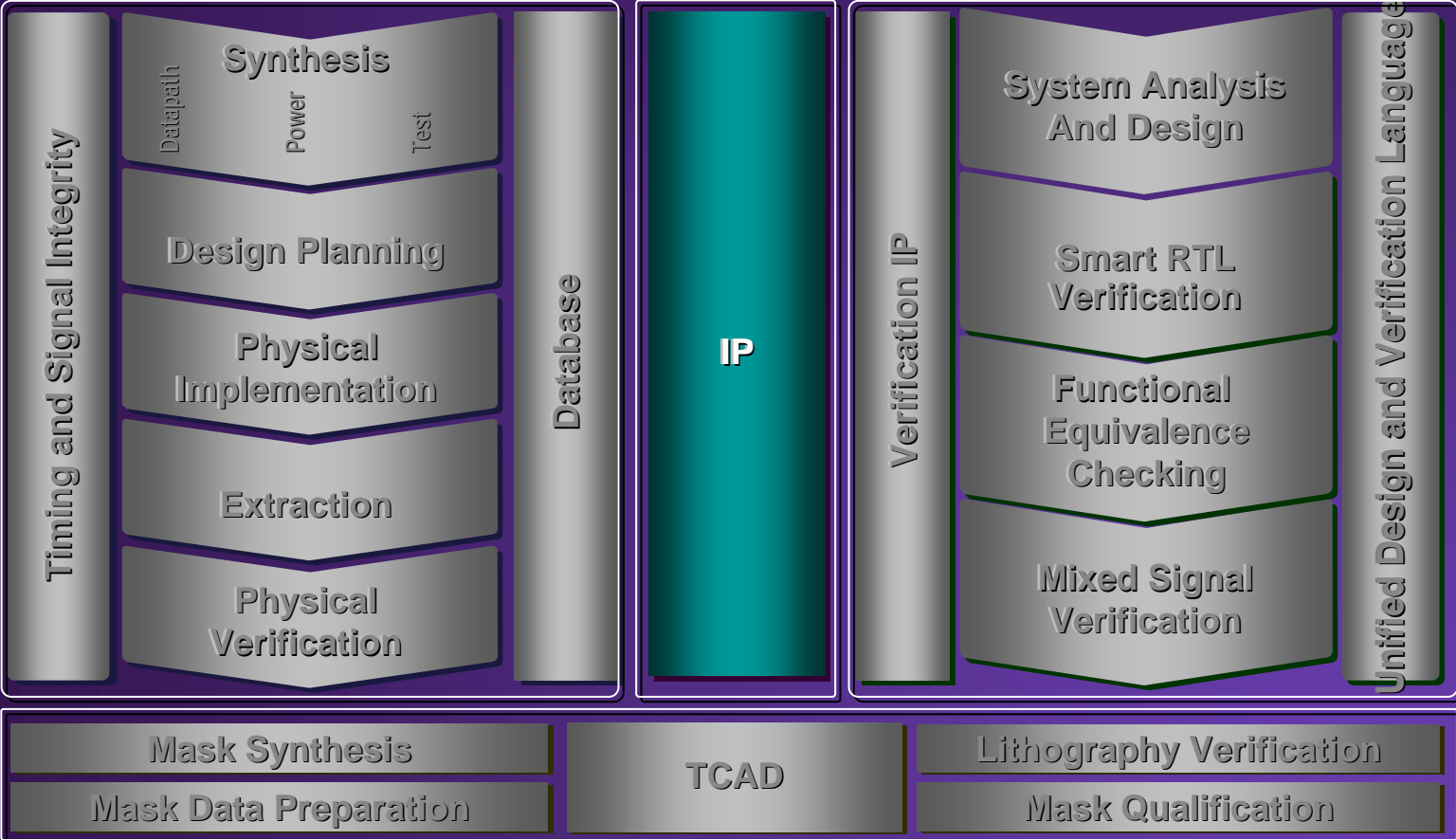
Technology Roadmap

1 μ m .7 μ m .5 μ m .35 μ m .25 μ m .18 μ m .13 μ m .09 μ m .065 μ m

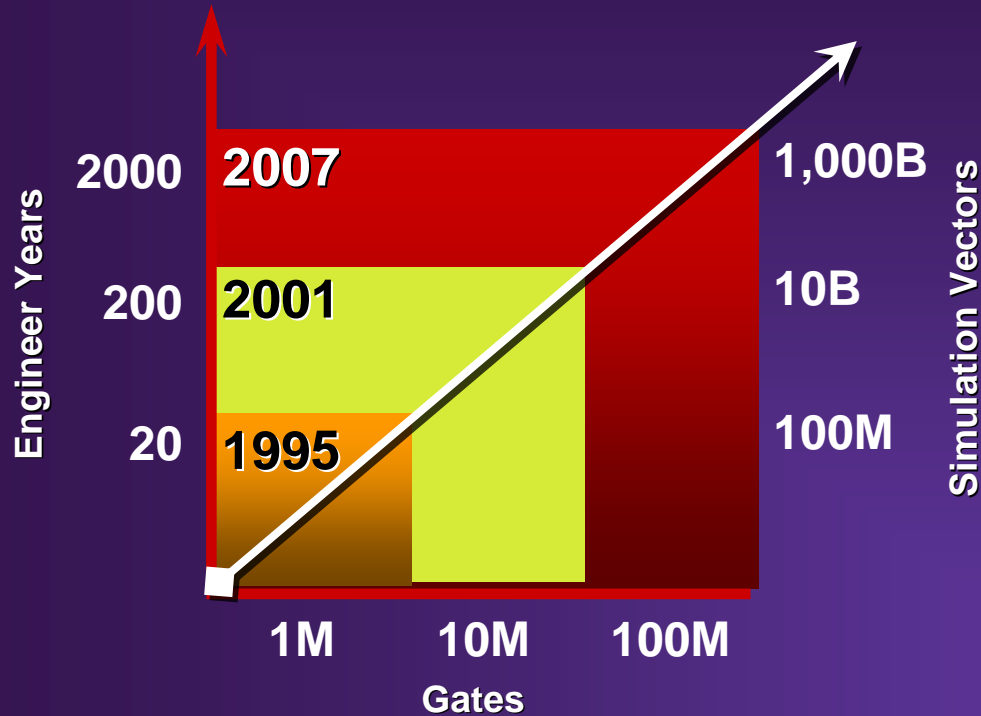


Cost

IP Based Methodology



The Designer's Escalating Problem

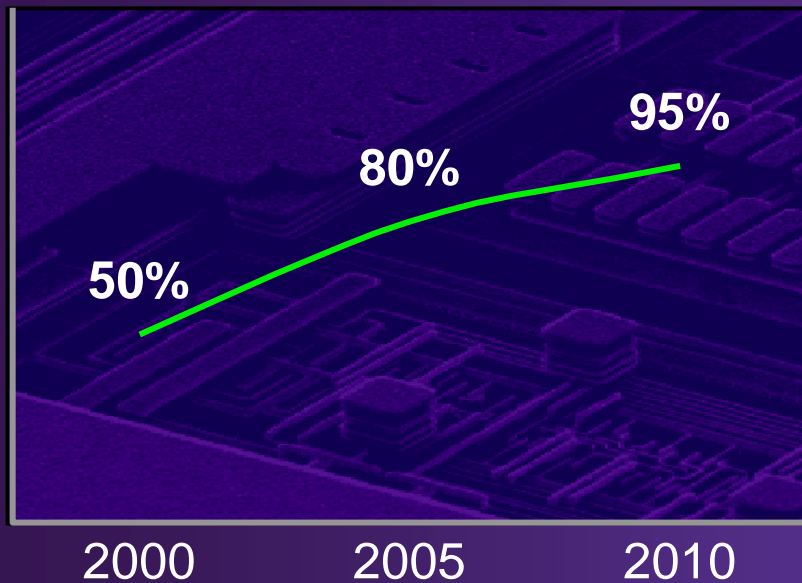


2,000
engineer years
to write
25M lines of RTL

1,000B
simulation vectors
to verify

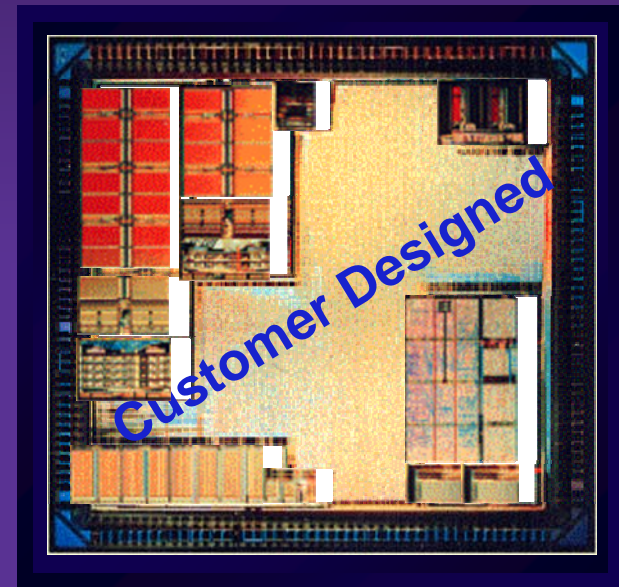
The Solution: IP Reuse

Pre-designed Blocks
as % of an SoC



Source: Dataquest, 2000

IP, Memory and SW
Increasing

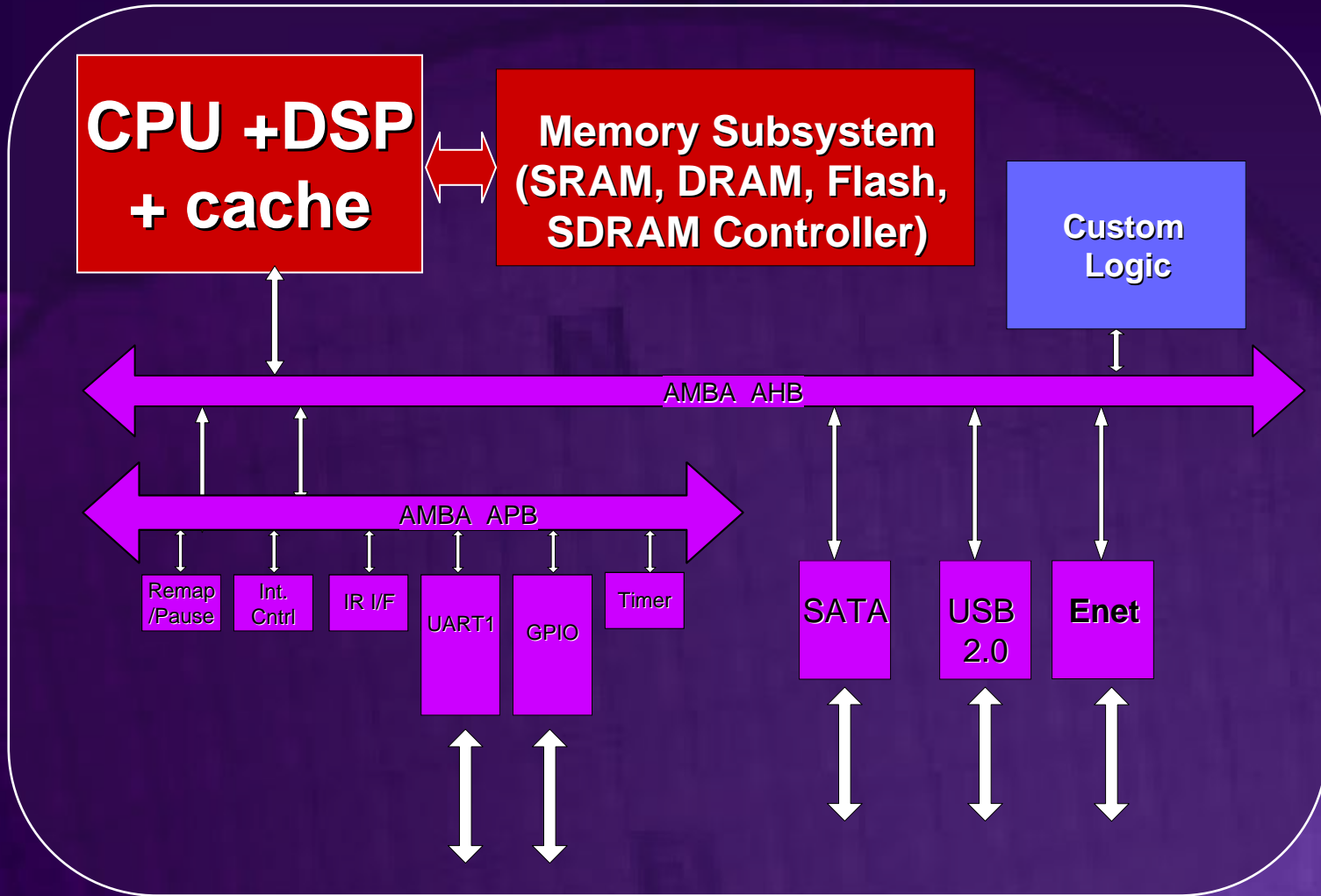


What Works

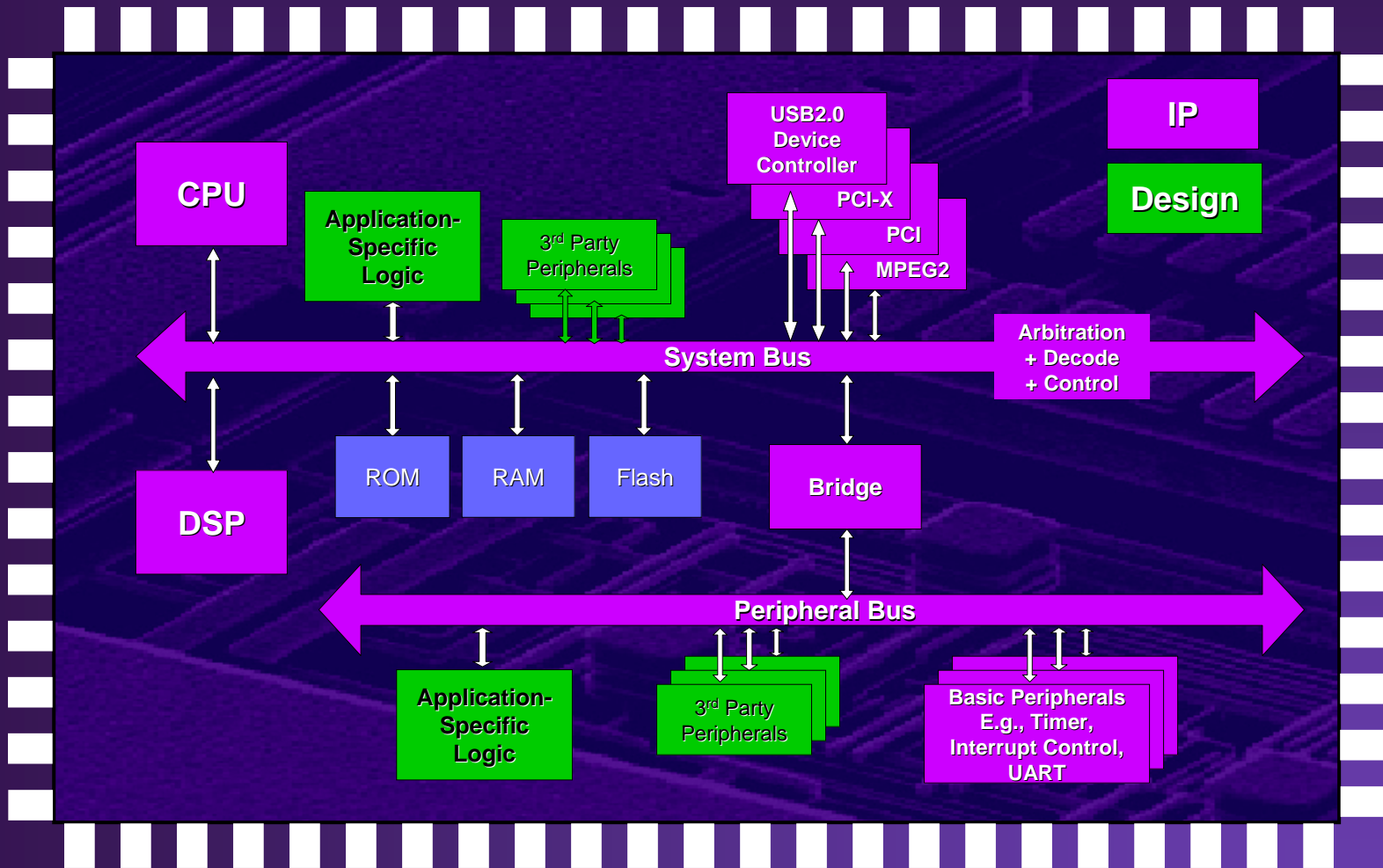
Semiconductors	\$141B
Micros, DSP	\$43.4B
Memory	\$30.8B
ASIC, ASSP	\$37.8B
Analog, Discrete	\$28.0B

**Standards enable
large volumes**

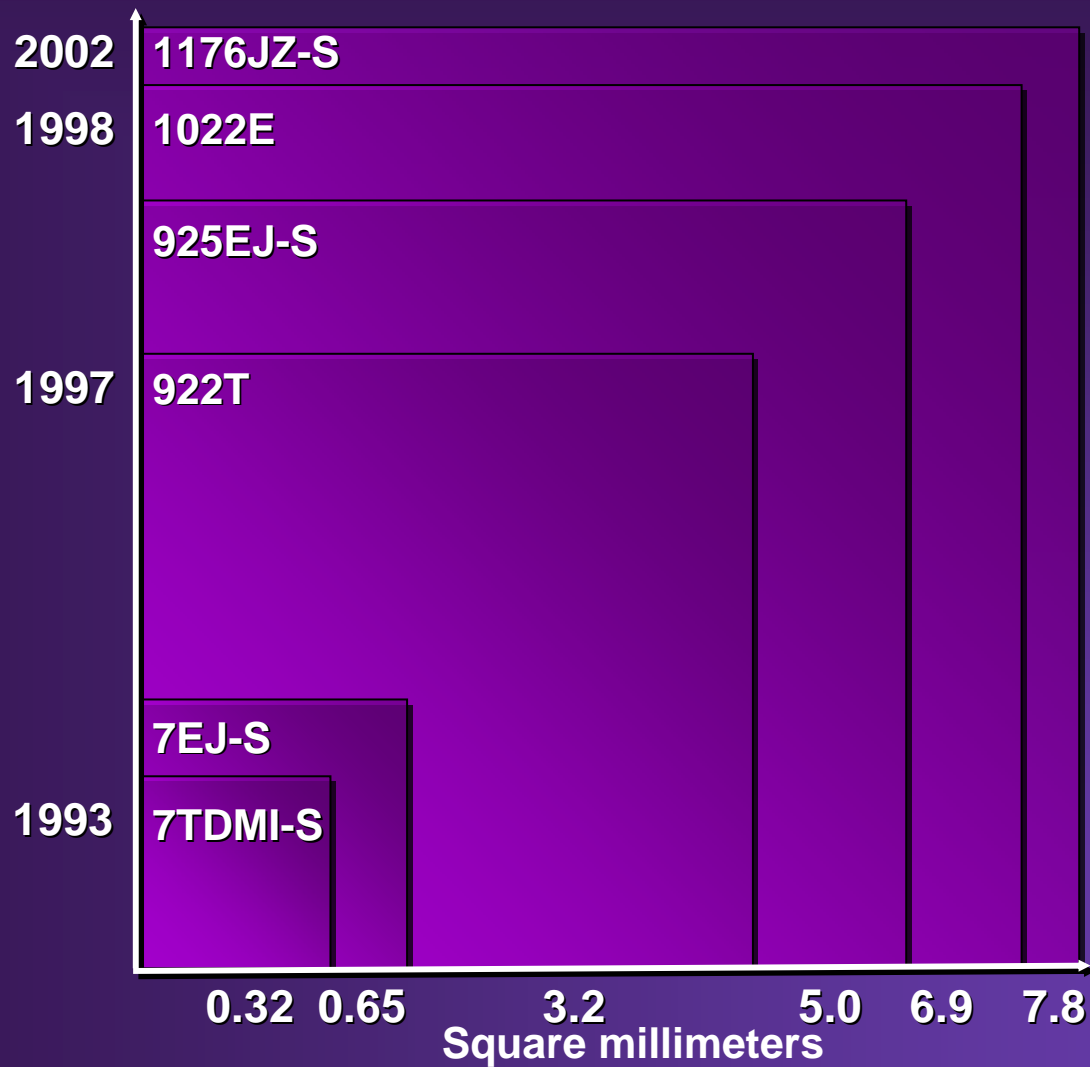
What's In An Soc?



From IP to Platform-Based Design



Increasing Size of Cores

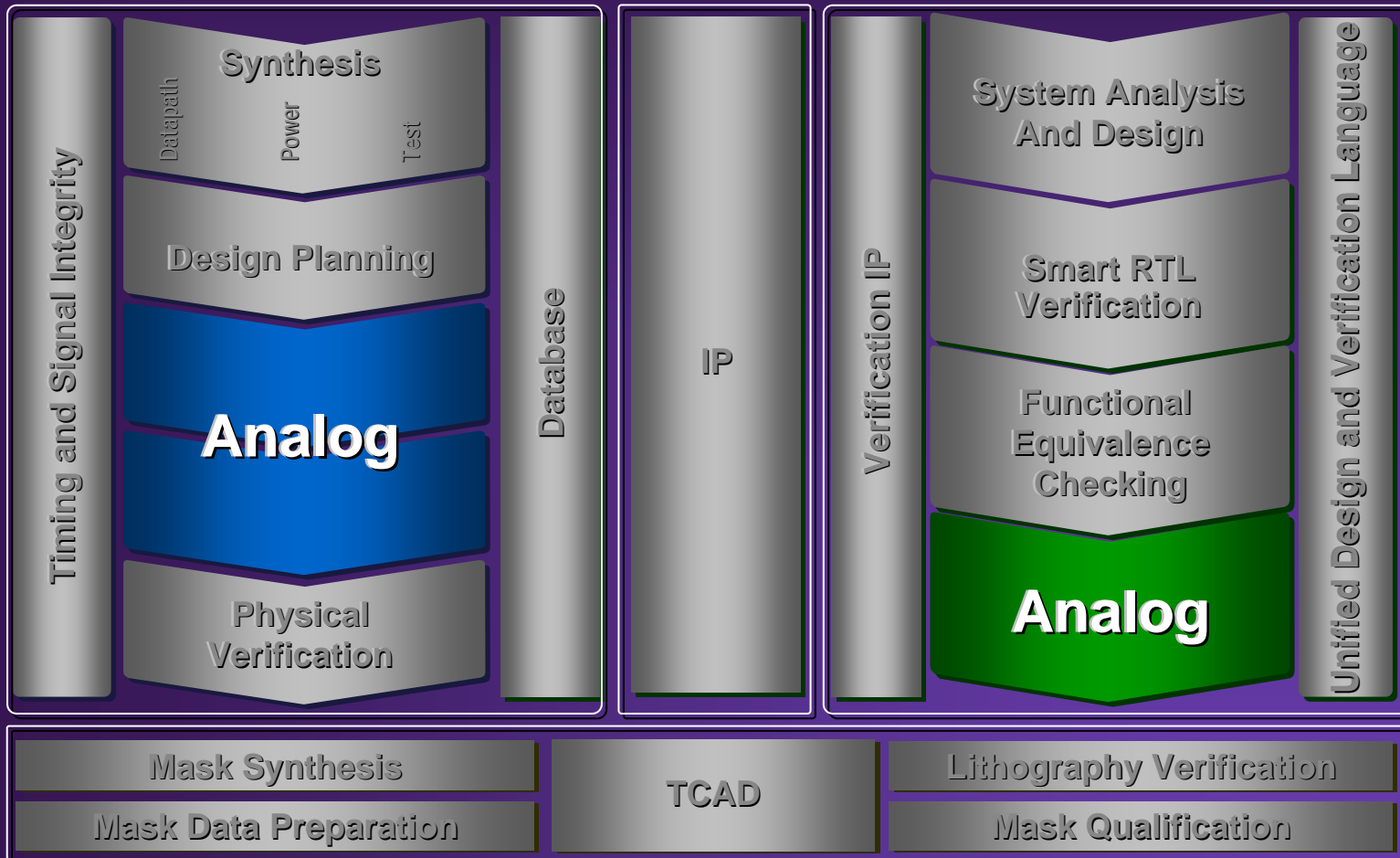


Future Trends



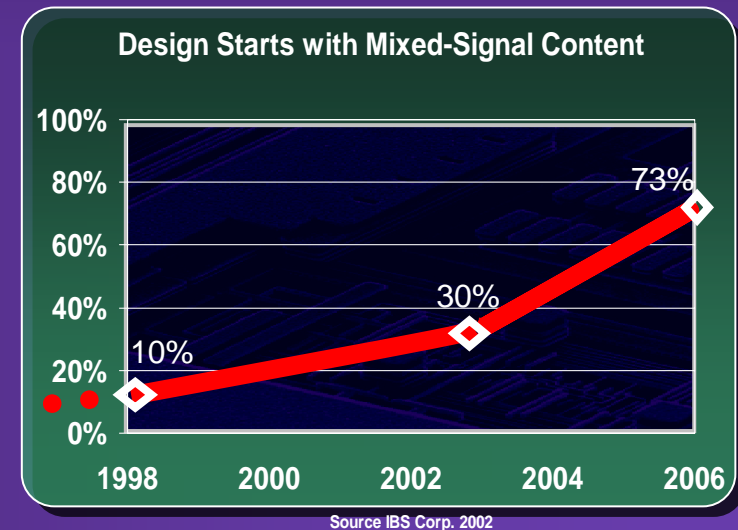
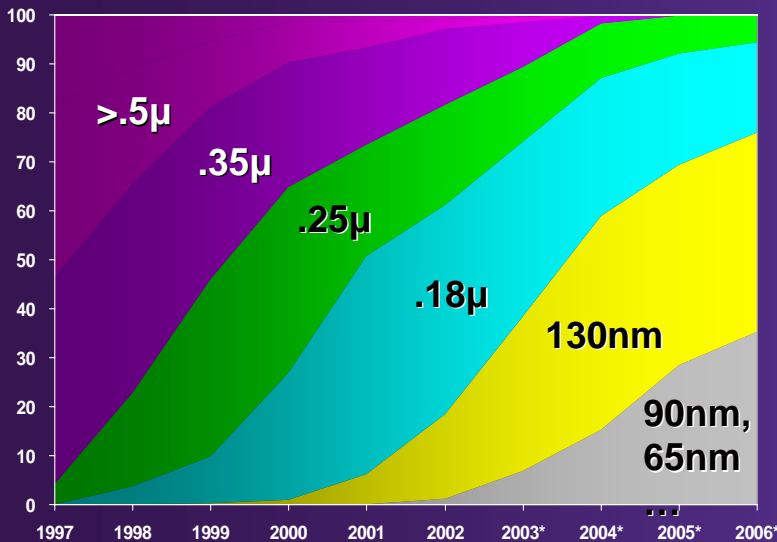
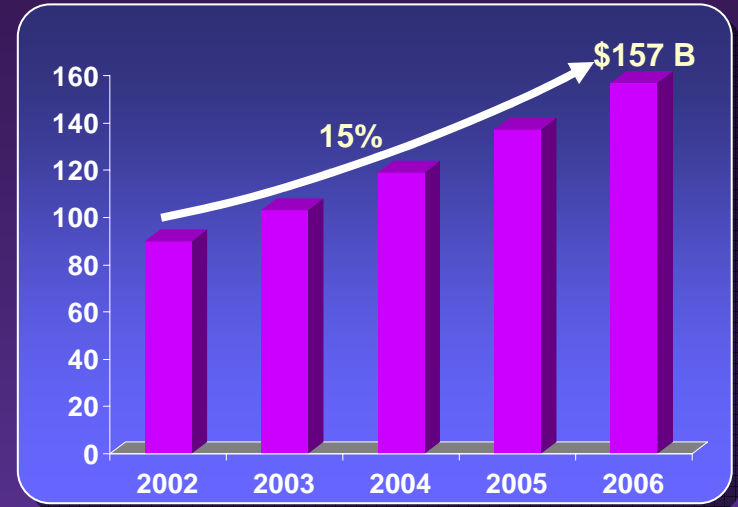
- IP reuse to increase to over 90% by 2010
- IP based design methodology
- IP diversity matters
 - It is kept in check by standards
 - Processors, memories and busses define platforms
 - IP needs to work together – platforms
- IP vendor size matters
 - IP needs to be certified by the vendor
 - The user certifies the vendor
 - Consolidation is unavoidable

Analog Design Flow

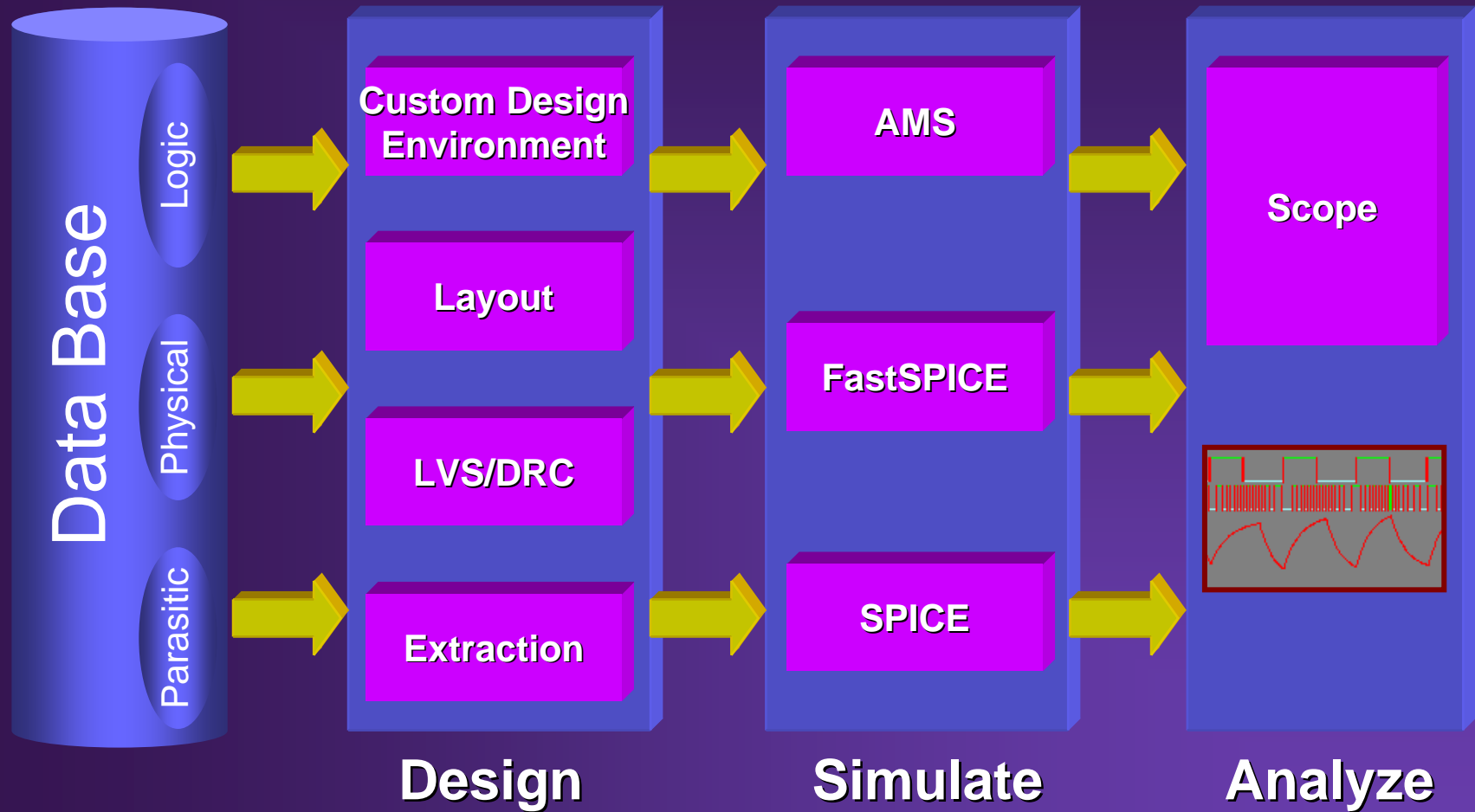


Mixed-Signal Design Trend

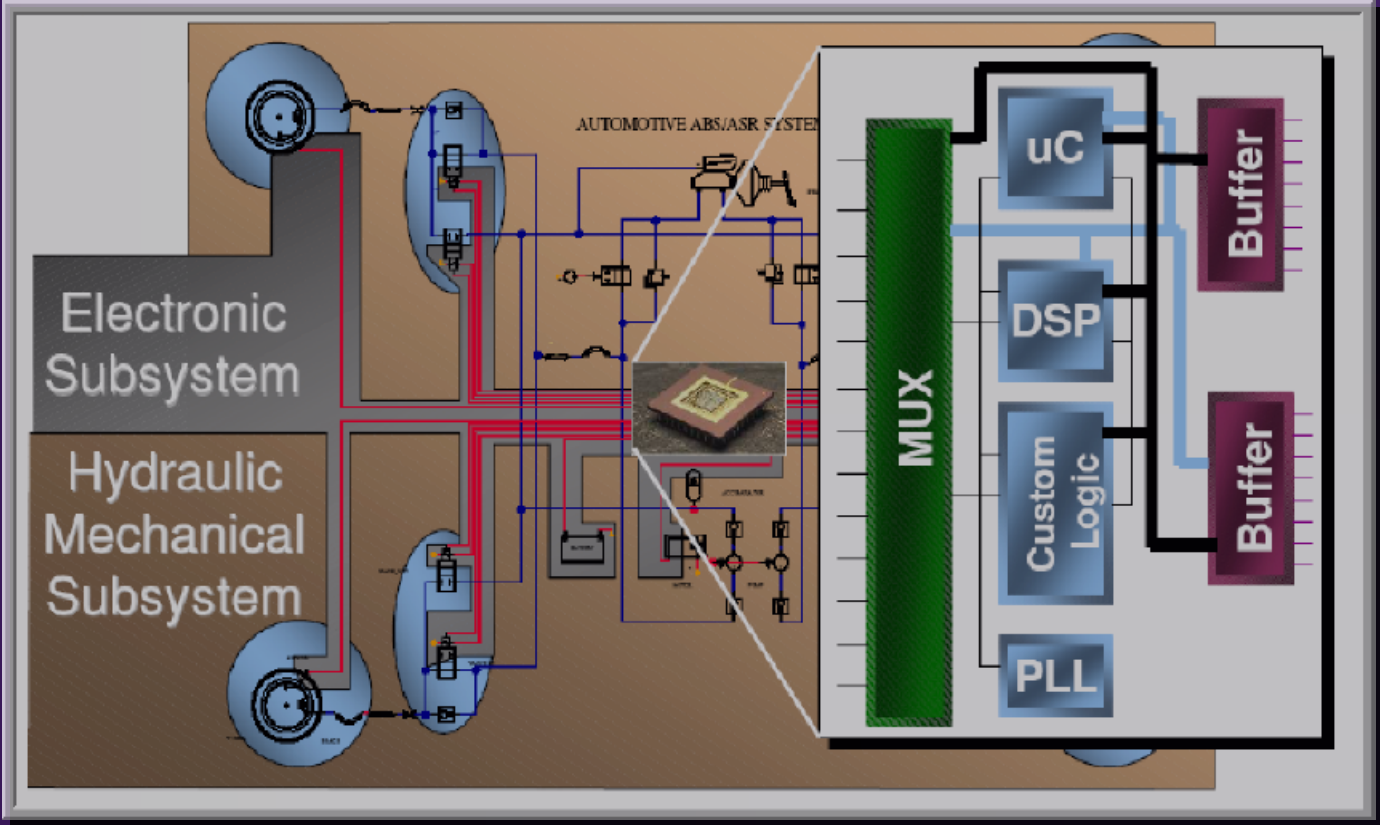
Fastest Growing IC Applications



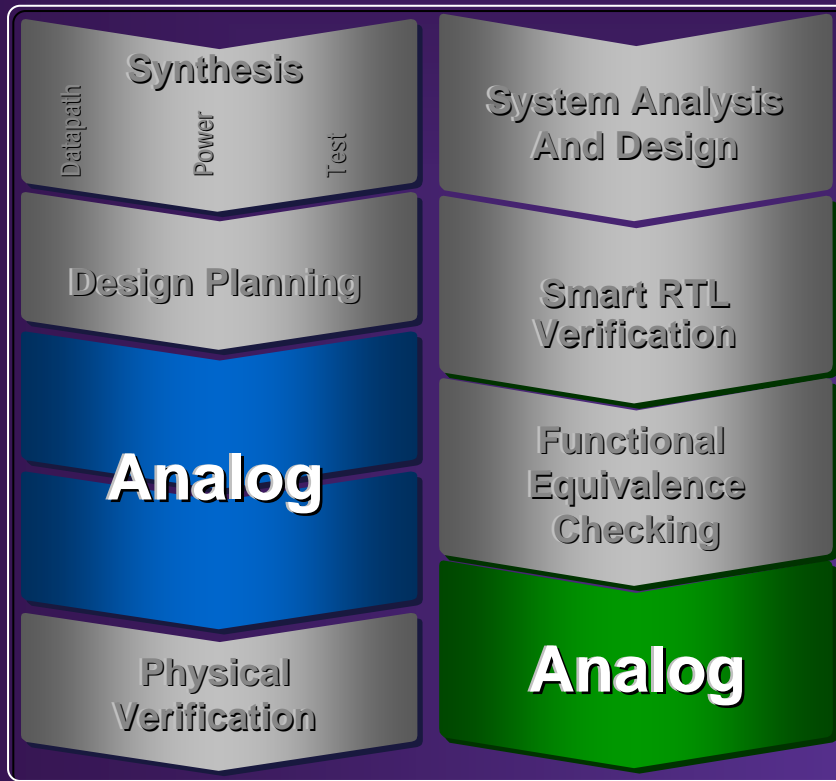
Integrated Custom & Mixed-Signal Analog Design Tools



Example: Saber

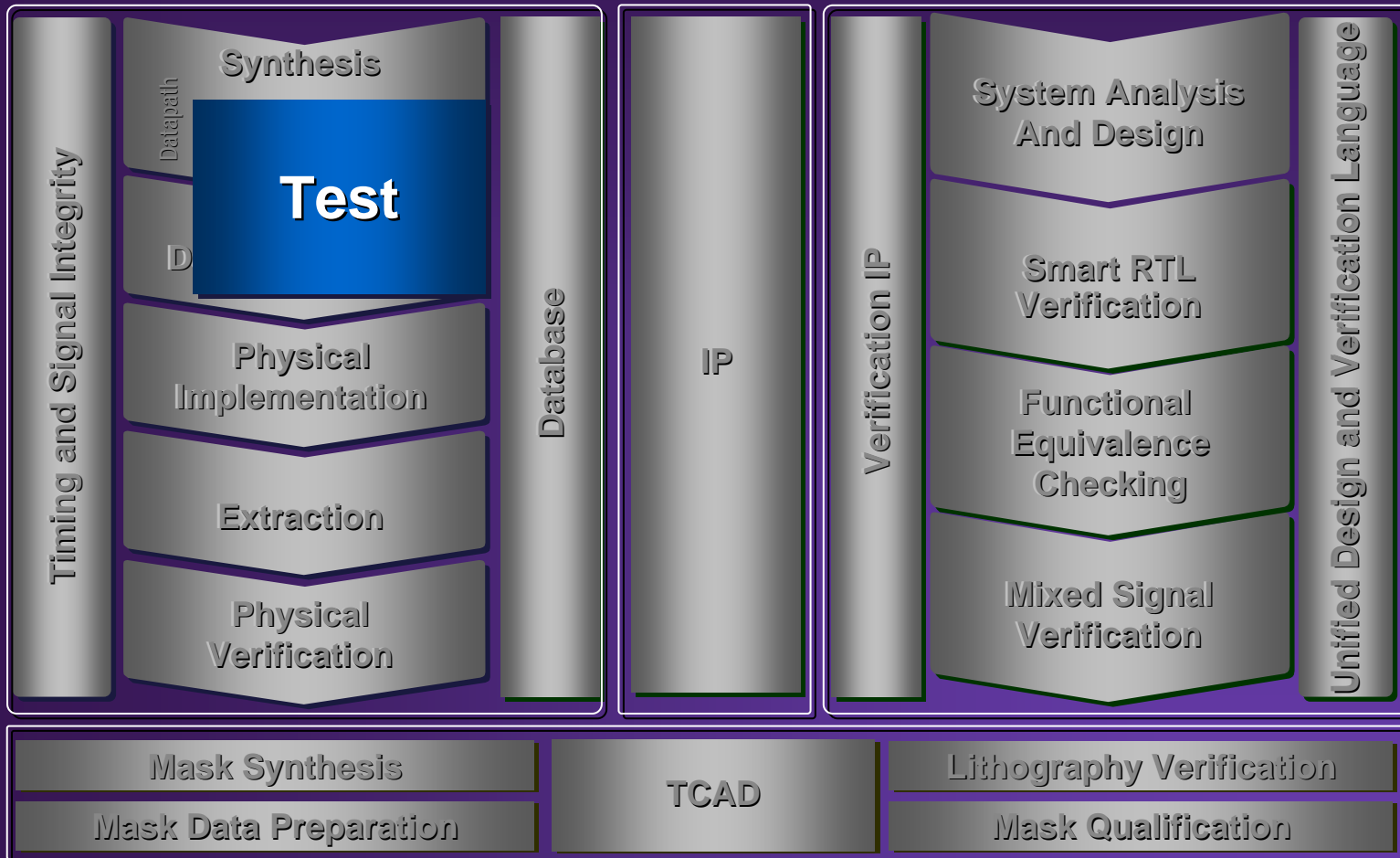


Future Trends



- More mixed signal design
- Includes also electromechanical, hydraulic, ...
- More analog design automation
 - Sizing
 - Physical design

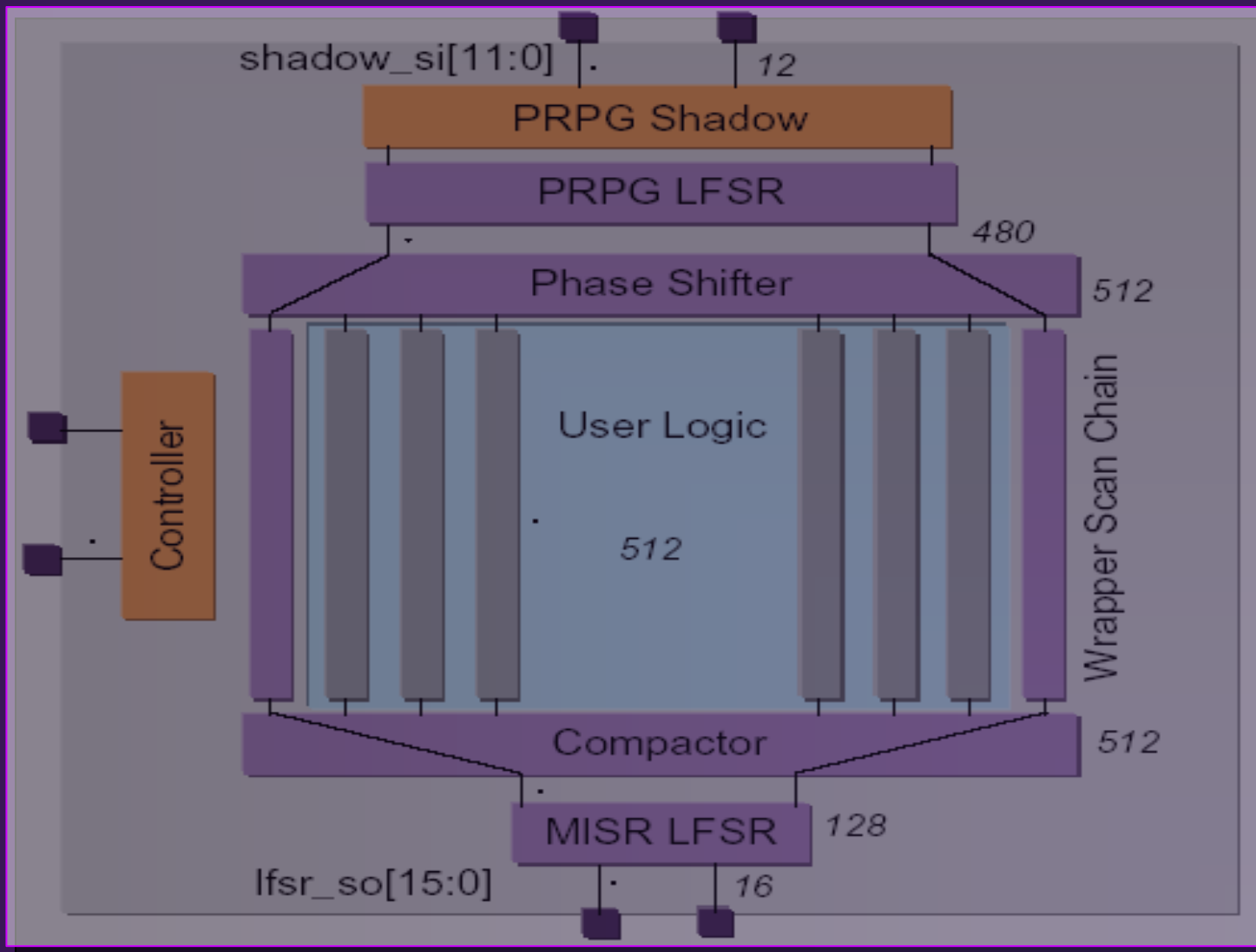
Built In Self Test (BIST)



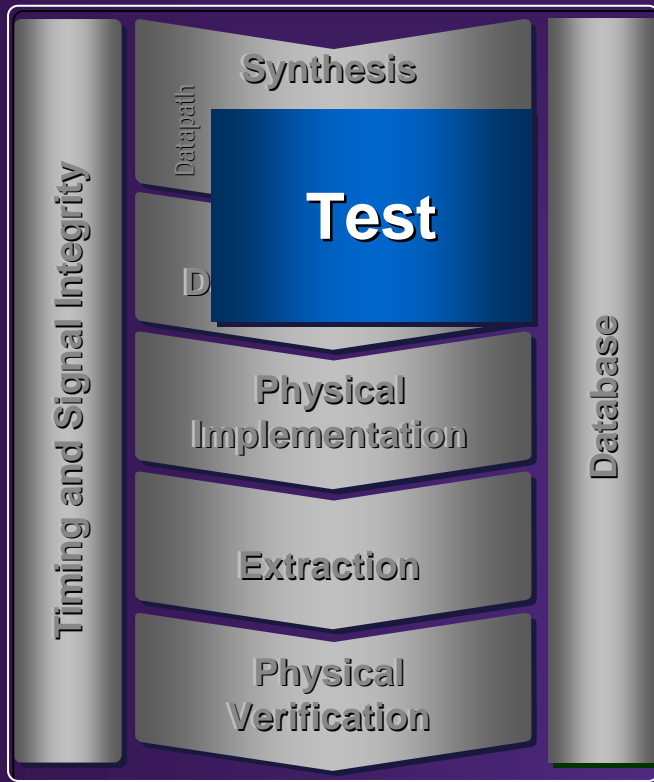
Design for Test



Synopsys SoCBIST Solution



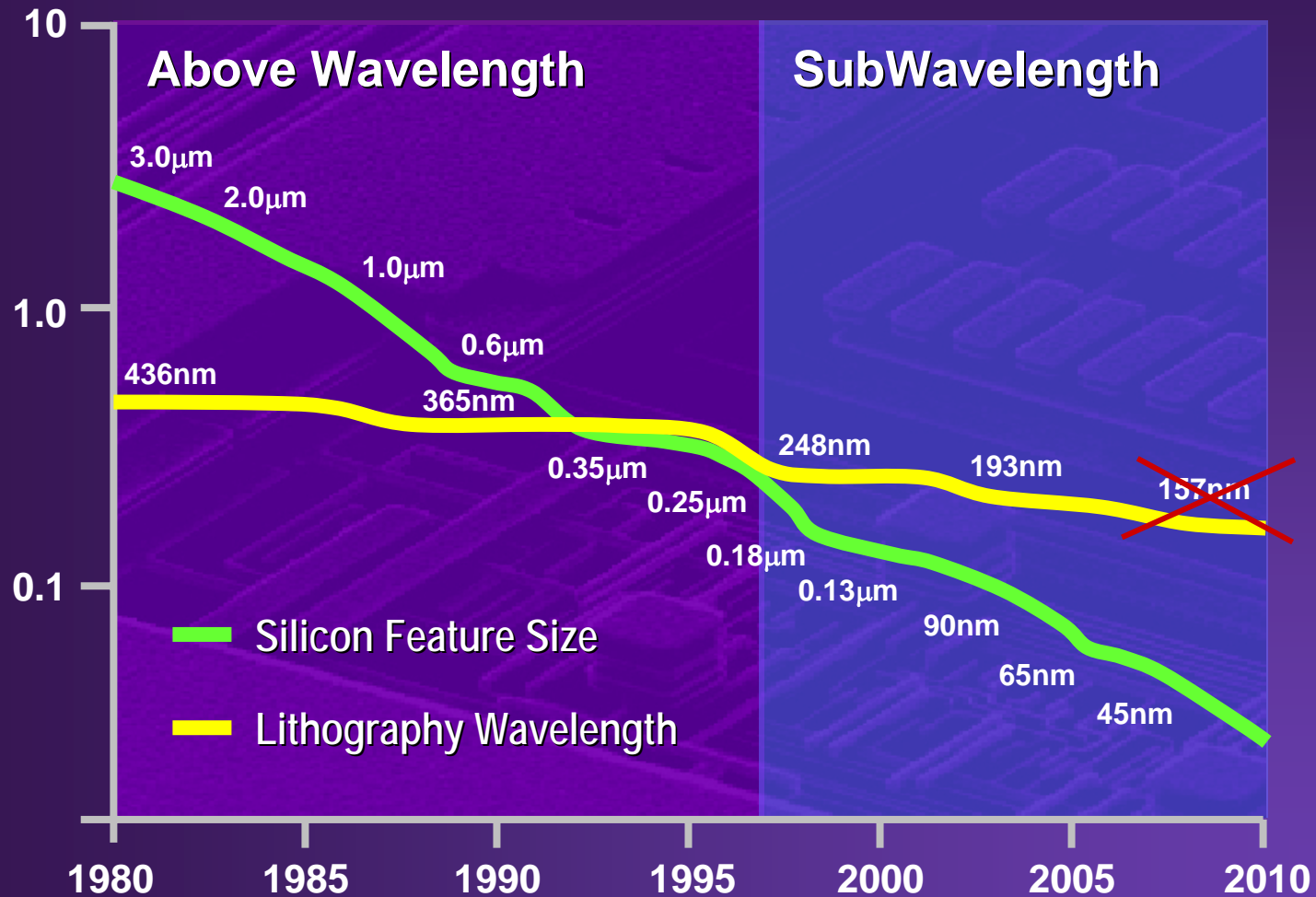
Future Trends



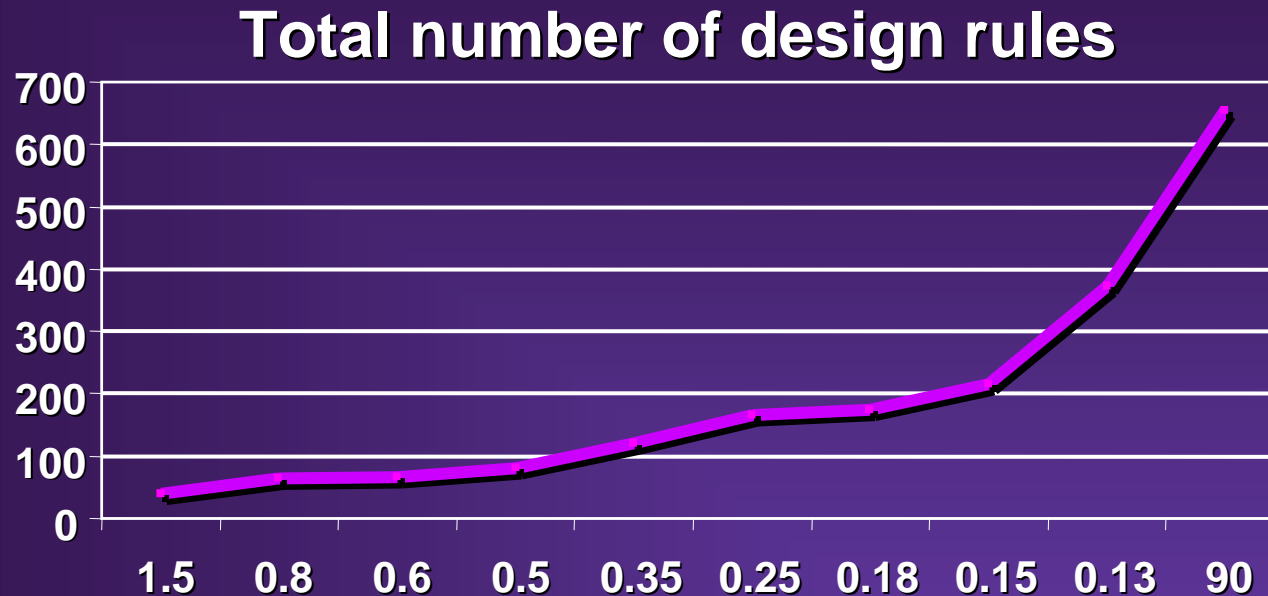
- Lower cost testers (structural test)
- Built-in self test
 - Memory
 - Logic
- Design for debug
- Fault tolerance

Subwavelength Lithography

Main Cause of Complexity



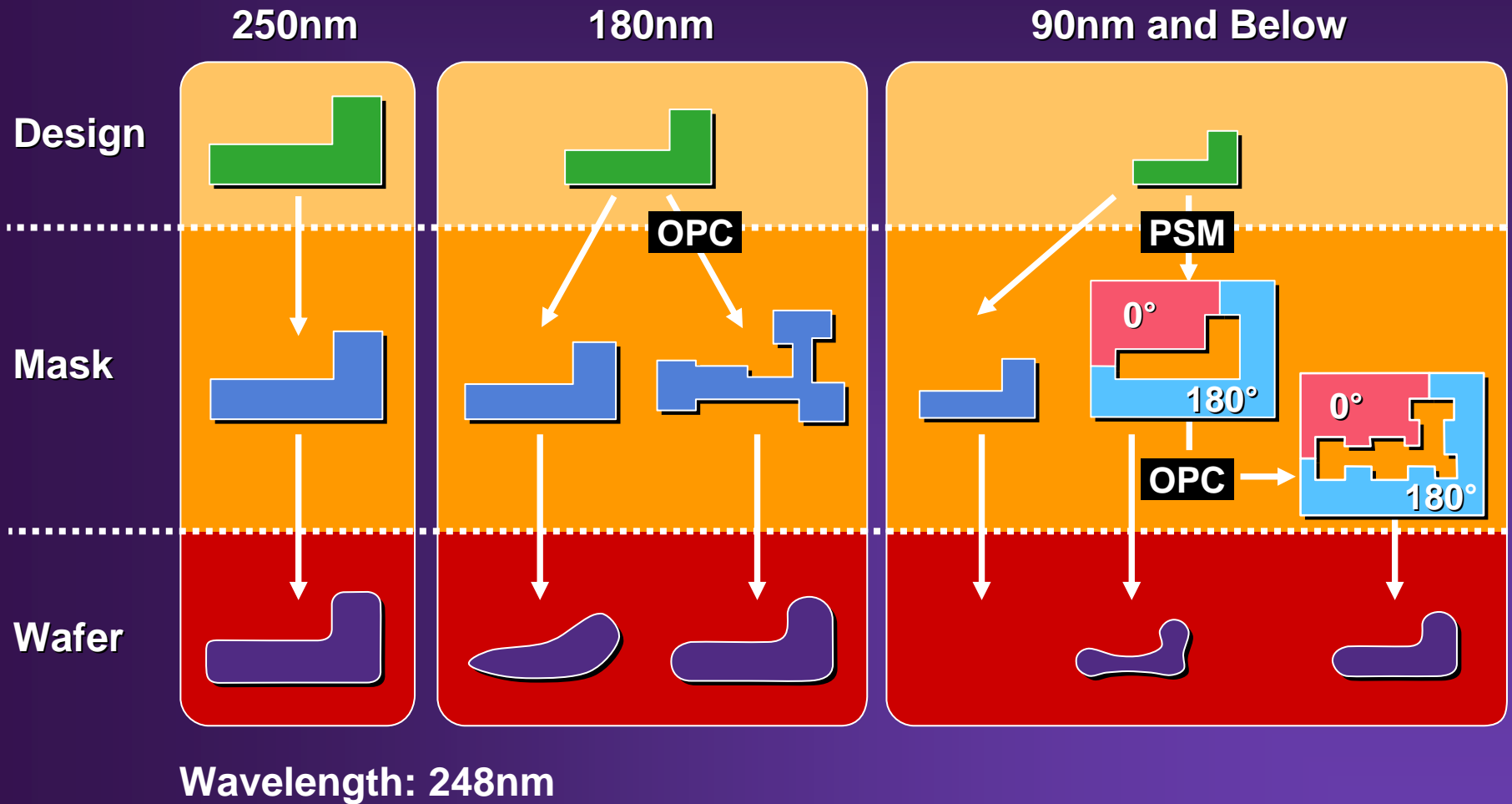
Subwavelength Design Rules



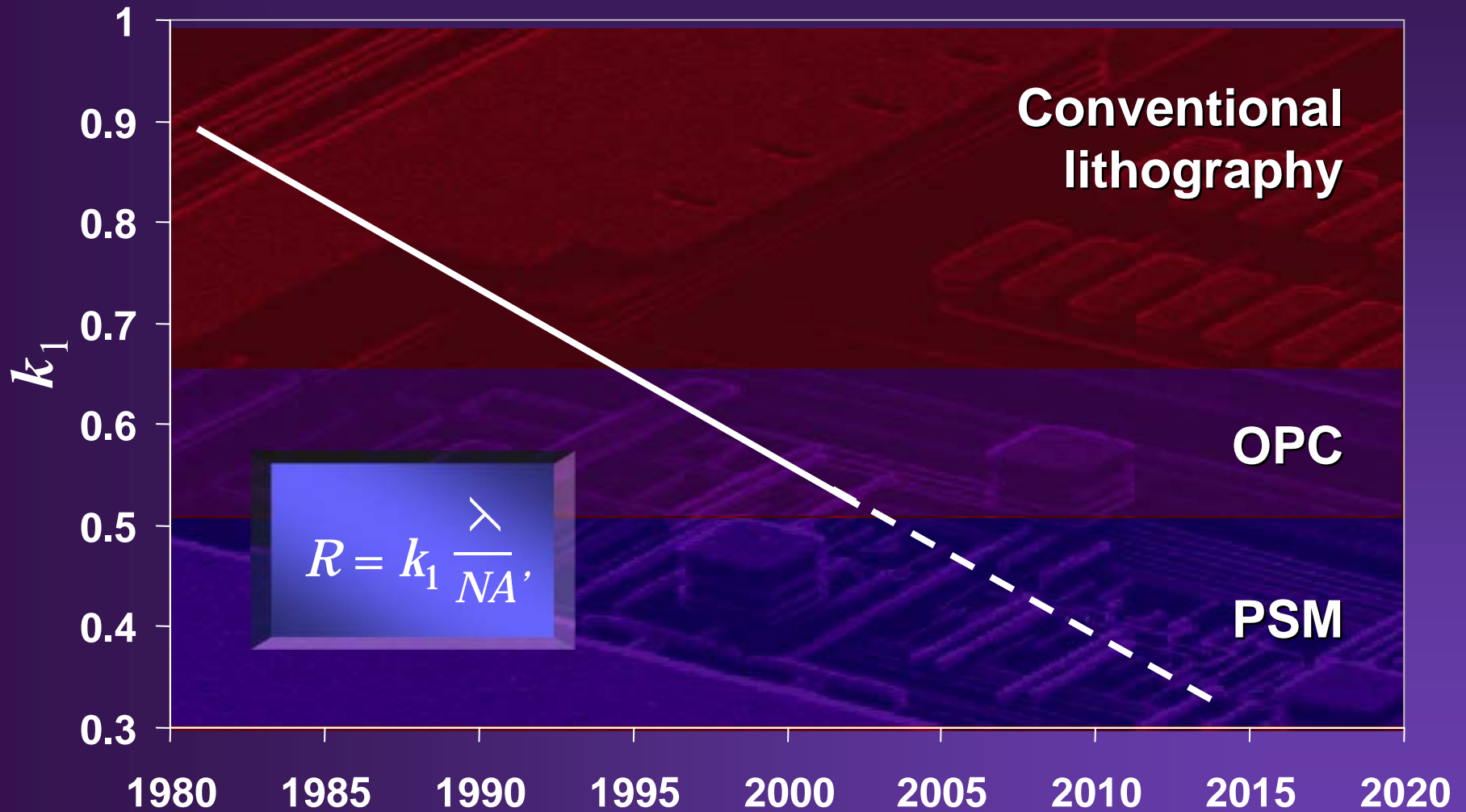
- **OAI/OPC/PSM create extremely complex, context-dependent design rules**
- **Design Rule Paradigm may be breaking down**

Mask Synthesis - RET

248nm Stepper

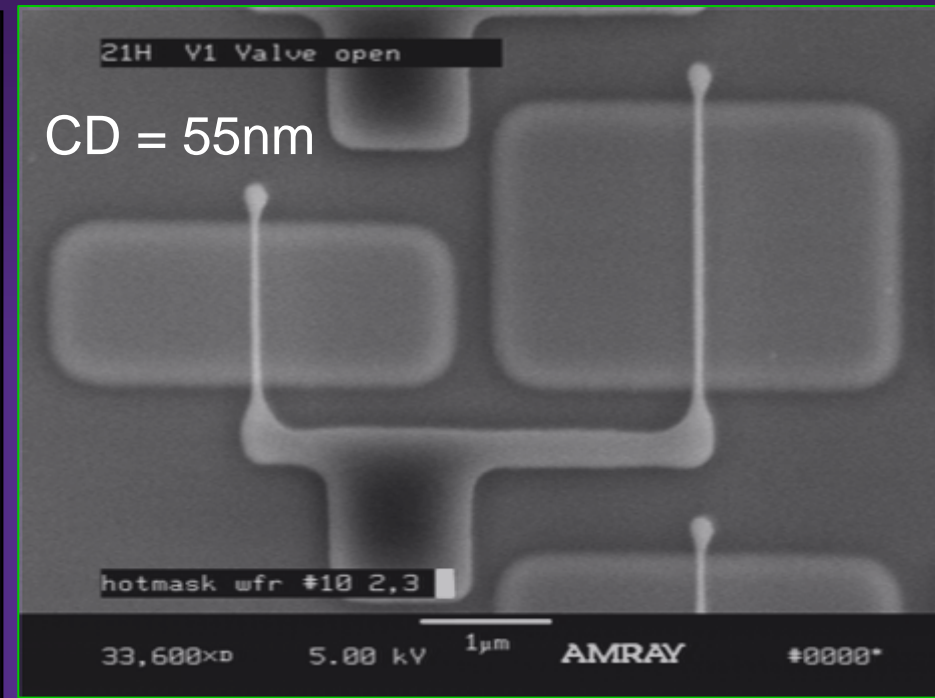
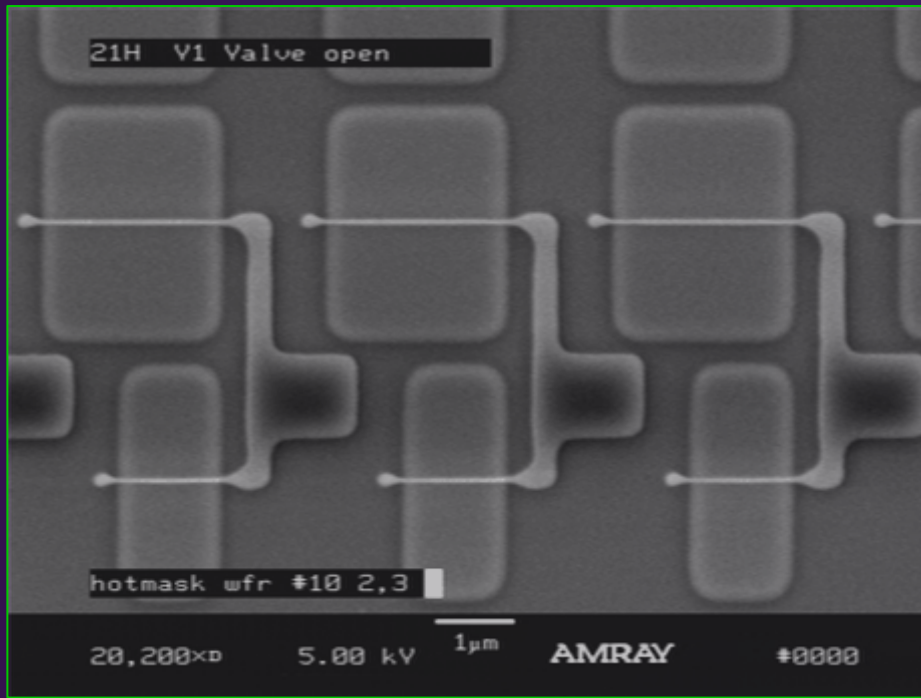


Evolution of RET



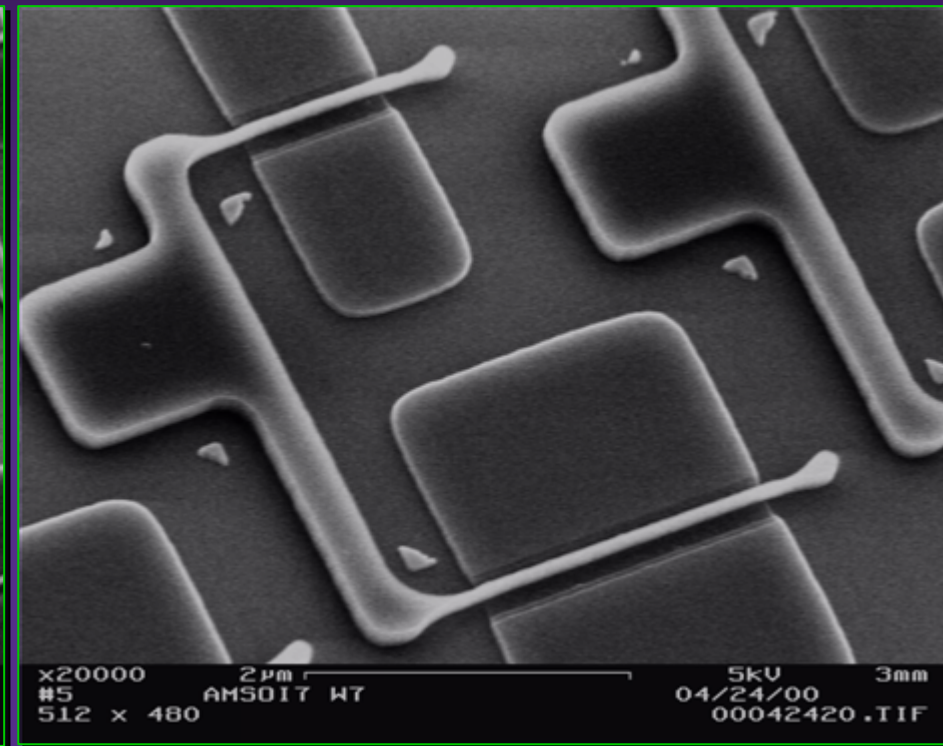
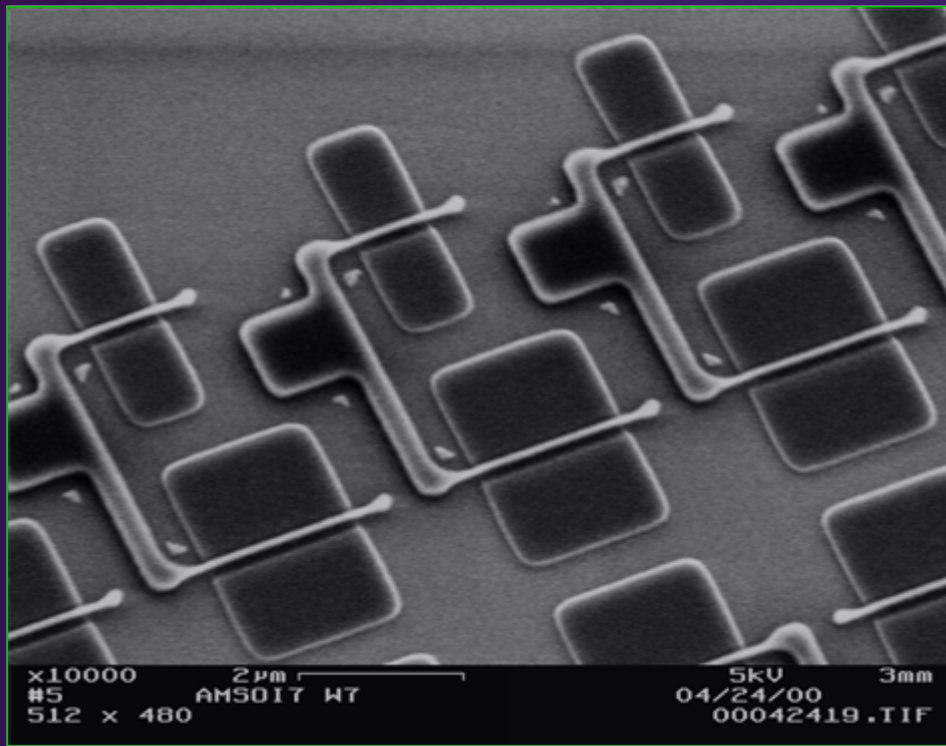
50nm Transistor Gates

Using Dark-Field Alternating Phase-Shift Mask (SNPS)



Resist on poly on patterned 600A islands
Canon EX-4 248 nm Stepper 0.6 NA 0.3 s
UV-5 on AR-3

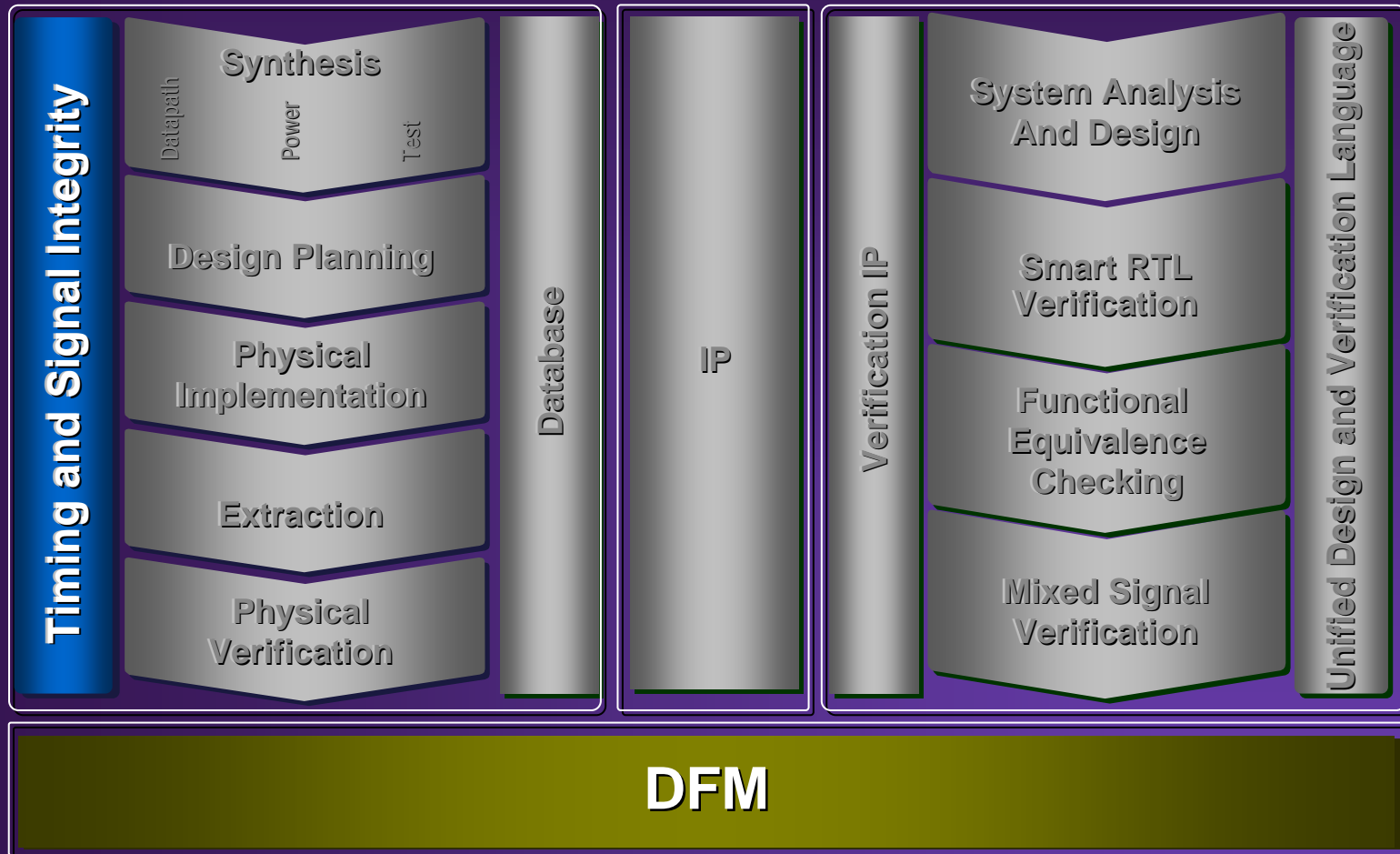
25 nm Transistors!



25-nm transistors produced with 248-nm lithography and AAPSM + OPC

Timing

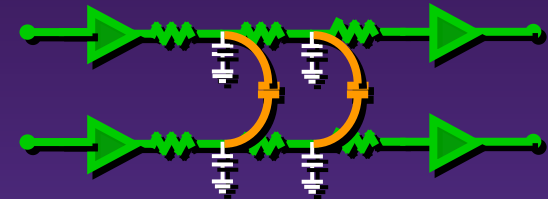
Timing In the Design Flow



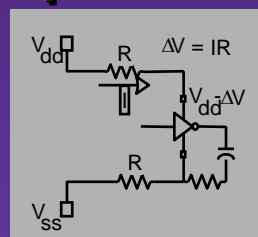
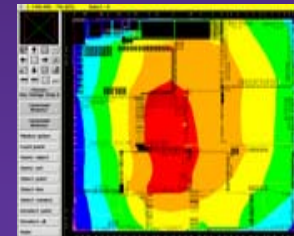
Shrinking Geometries Make Timing and Signal Integrity A Growing Problem

- Shrinking noise thresholds
- Increasing coupling capacitance
- Increasing current density
- Inductance
- More statistical variation

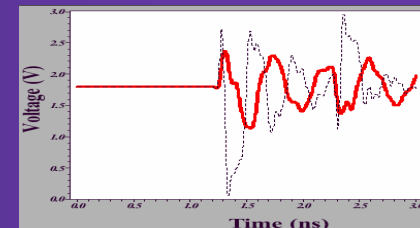
Crosstalk



IR Drop

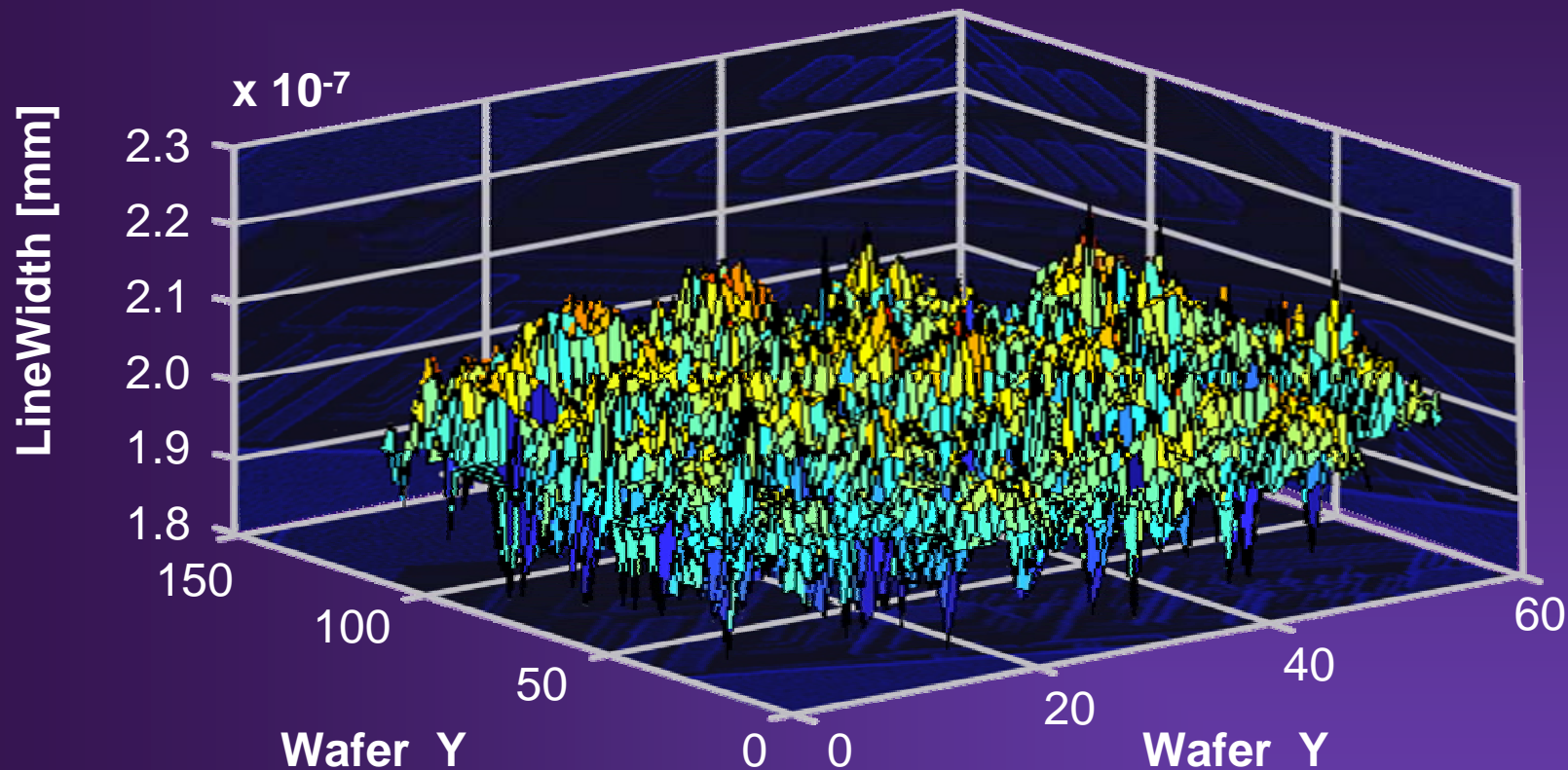


Inductance



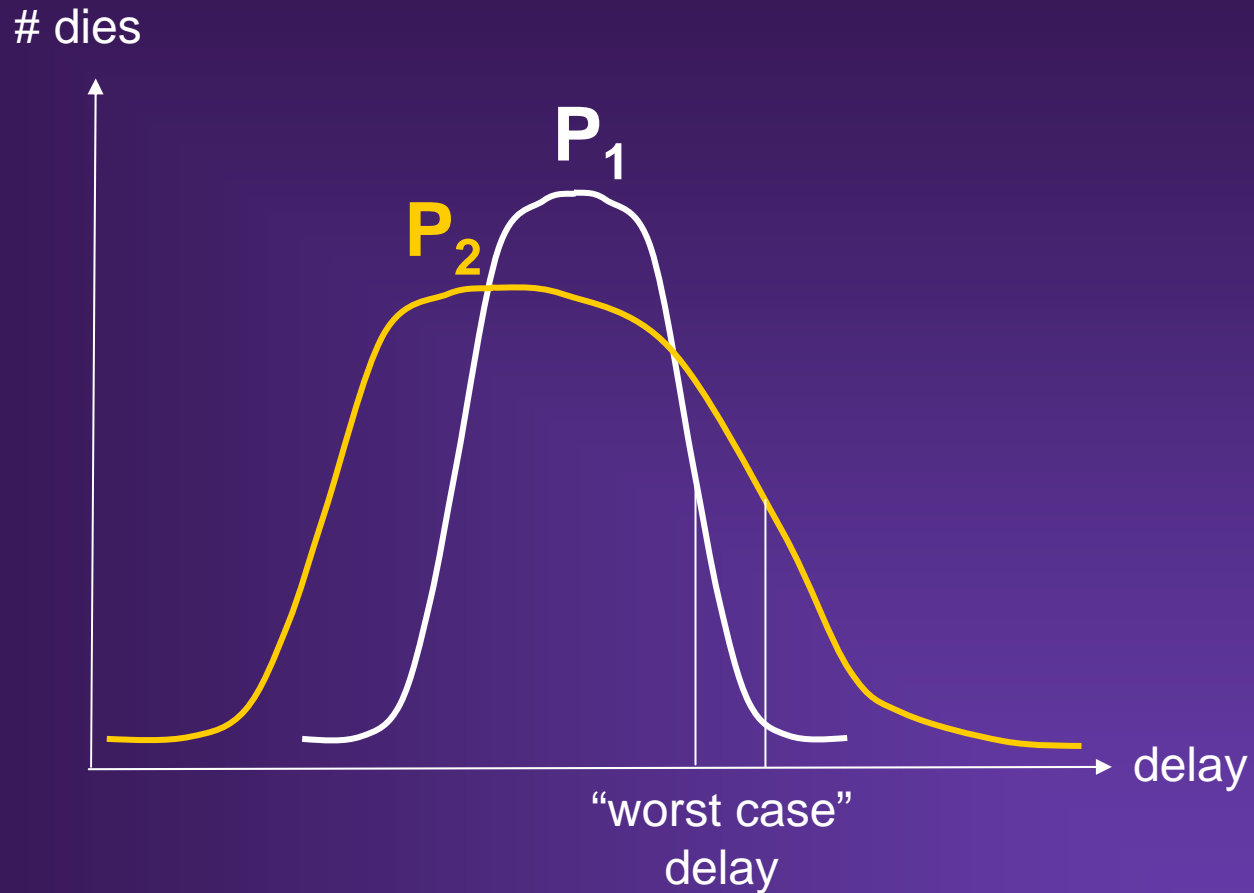
CD Variation Across a Wafer

Wafer Map for No-DPC Horizontal Isolated Structures



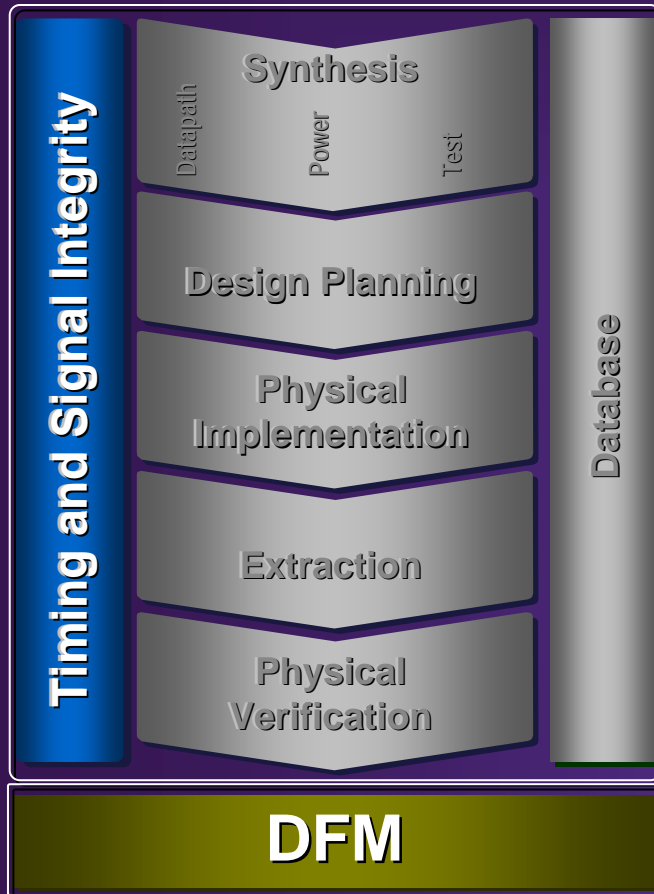
Incorporate analysis of timing variation into statistical timing analysis

Variability



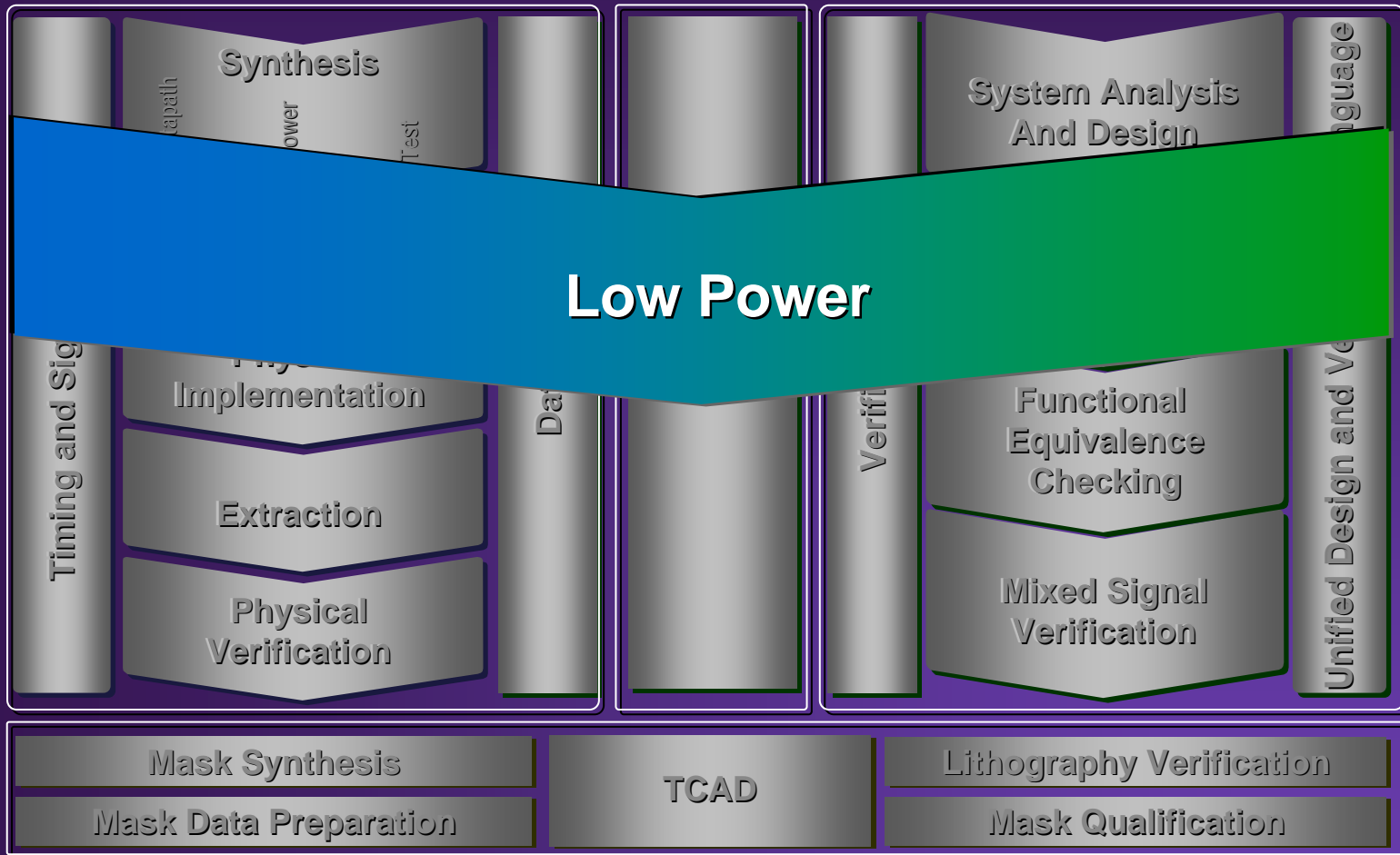
- Requires statistical timing analysis?

Future Trends



- Tools need to consider parasitics
 - Cross-coupled capacitance plus the Miller effect
 - IR drop (static leakage and dynamic IR drop)
 - Inductance
 - EM
- CD variation requires statistical analysis

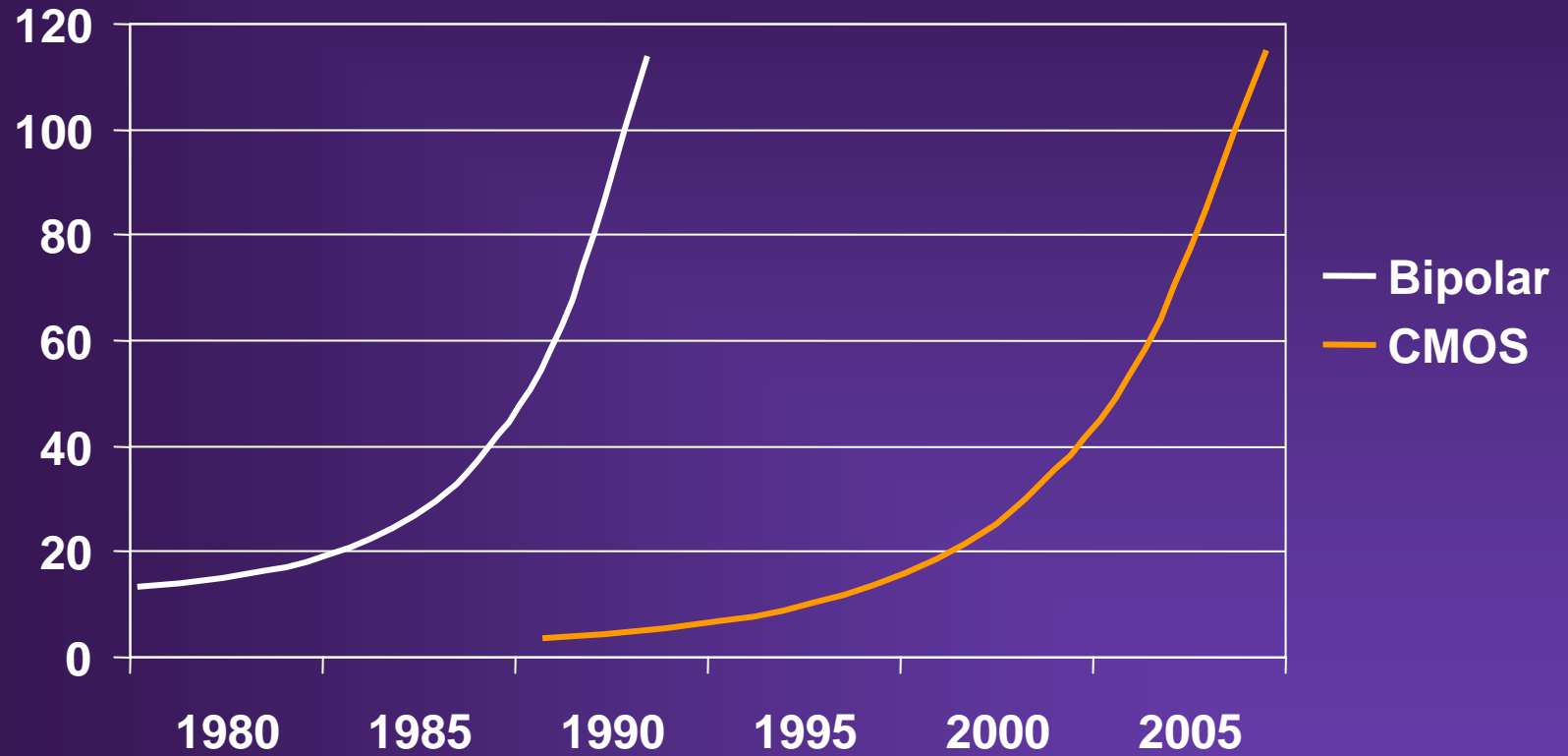
Low Power Design Flow



Power

Power Consumption

Watts



Key Power Management Areas

Low Power



Application

- Wireless
- Handheld
- Embedded systems

Concern

- Battery life
- Lowest leakage &/or dynamic power

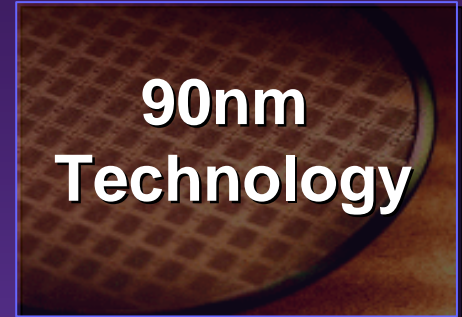
Thermal Management



- Microprocessors
- Graphics/multimedia
- Networking/telecom

- Thermal management
- Packaging, cooling cost

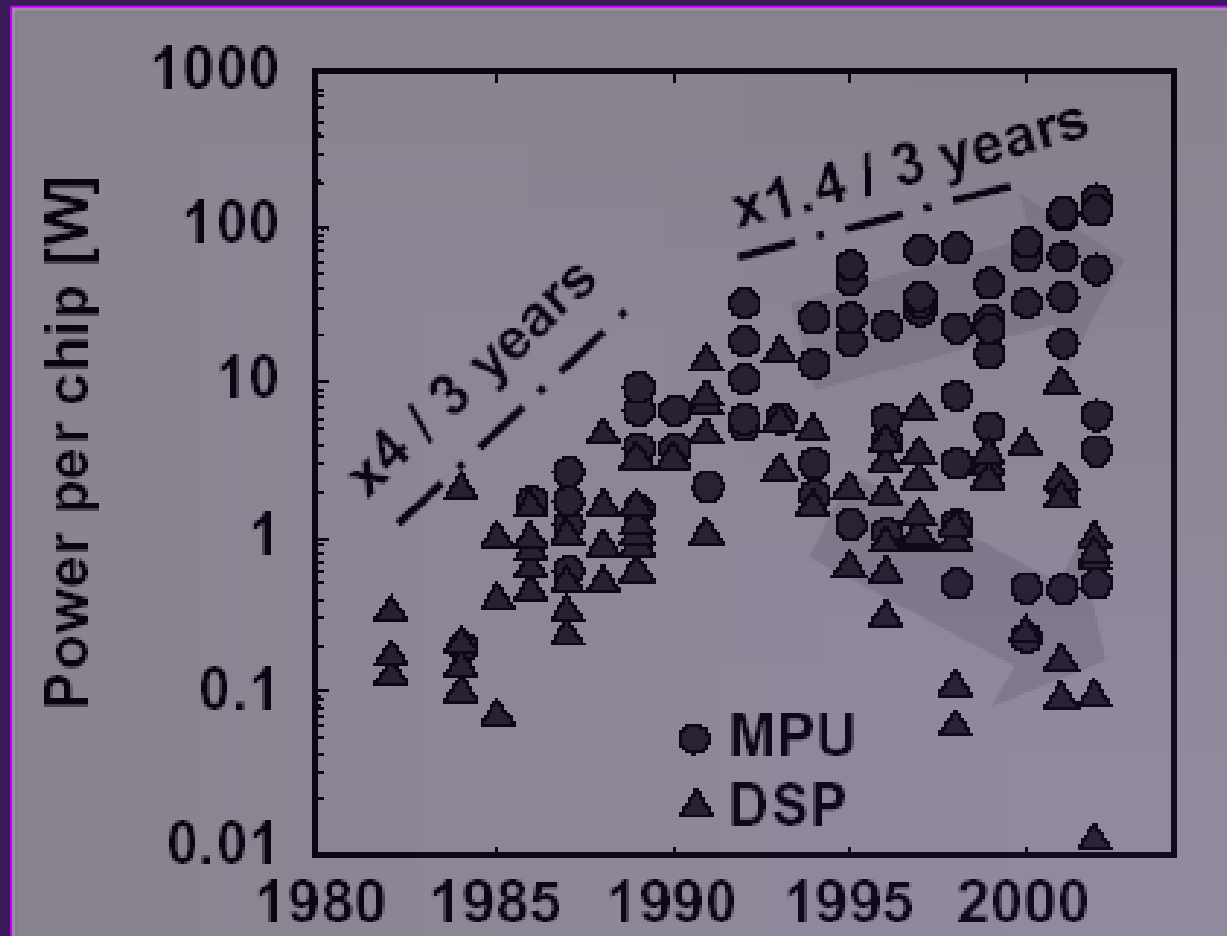
Physics



- Every design @ 90nm

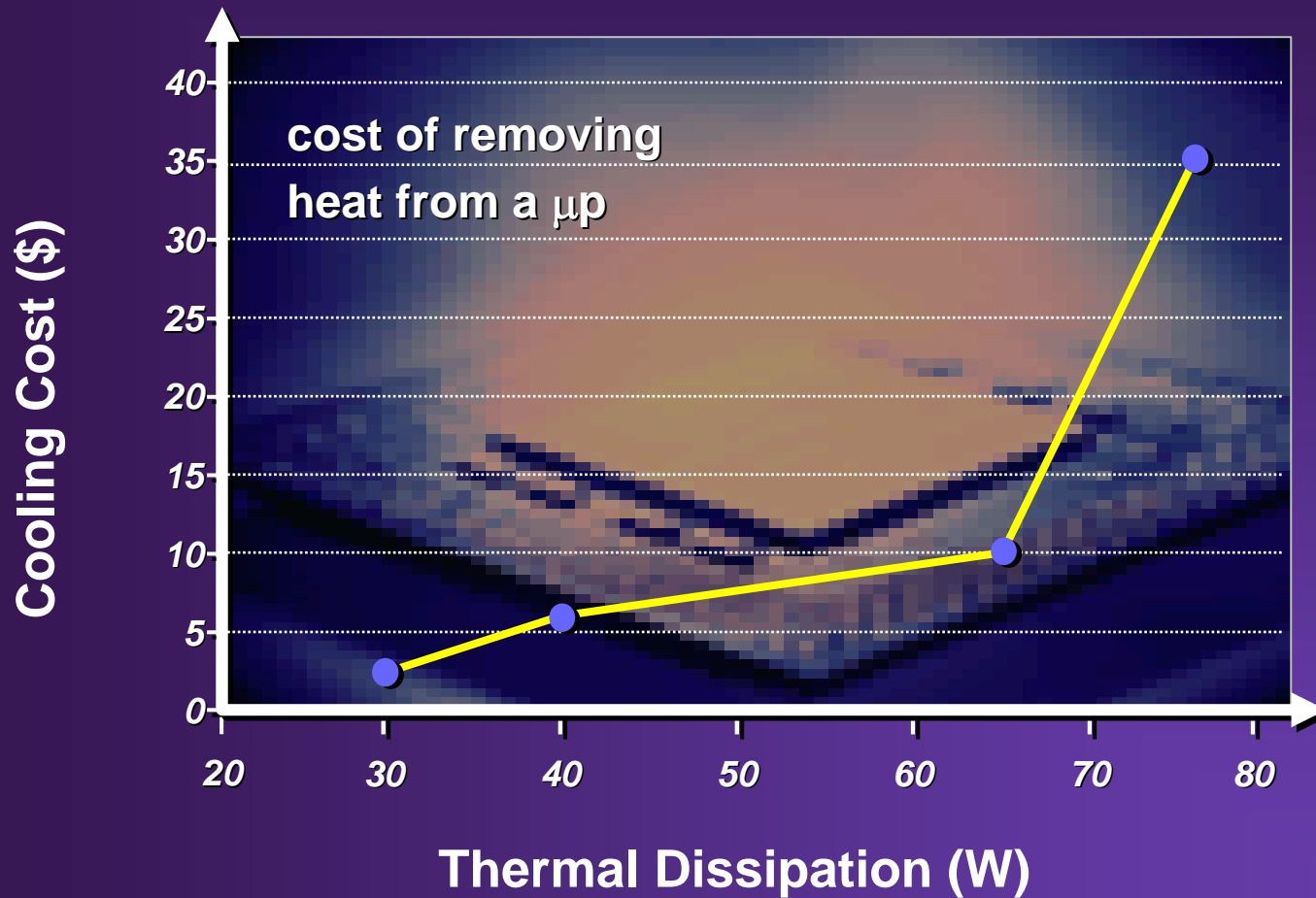
- Leakage power
- IR-drop
- Electro-migration

Hottest Chips in ISSCC

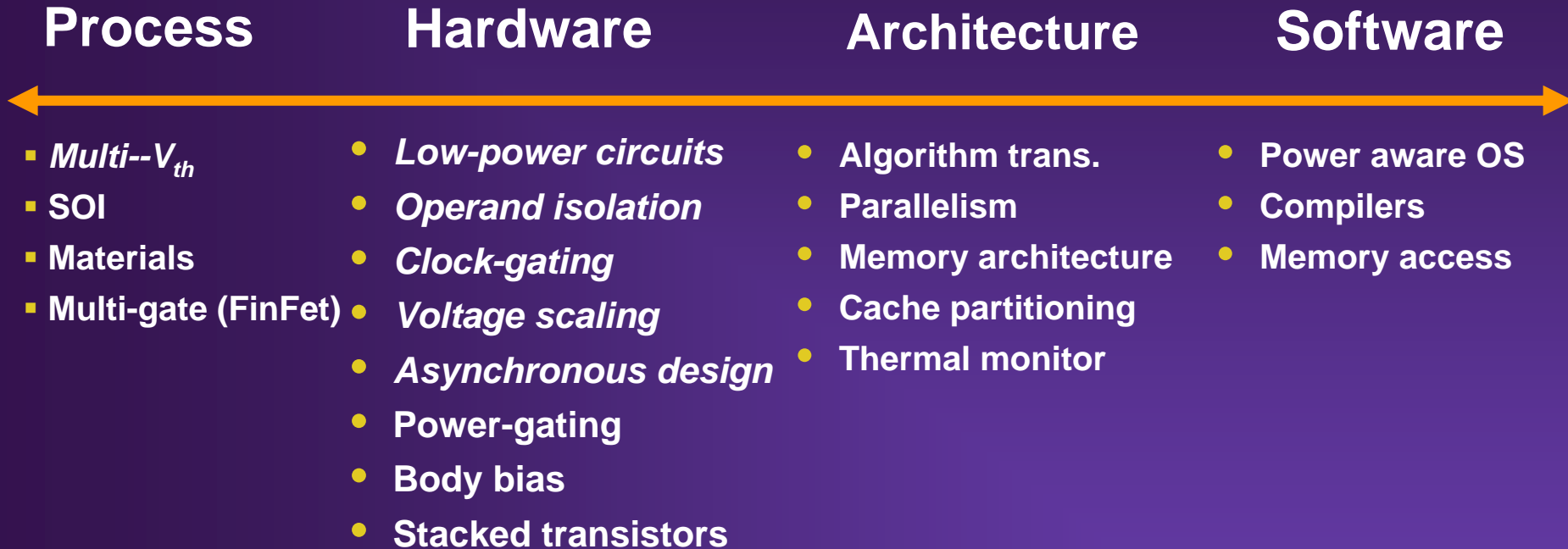


T. Kuroda, Keio Univ.

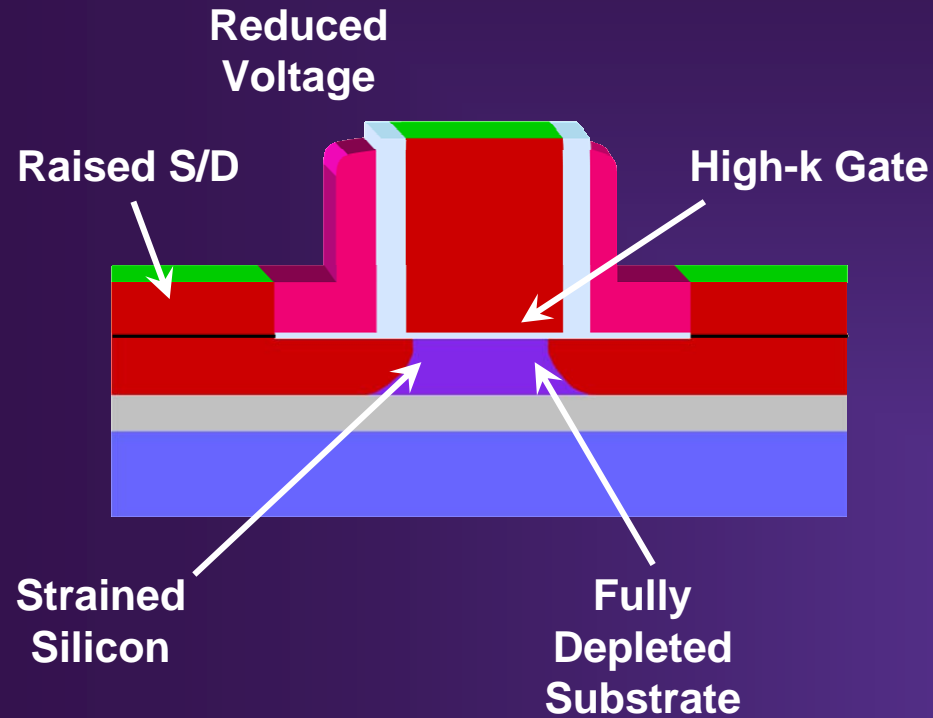
The Rising Cost Of Power



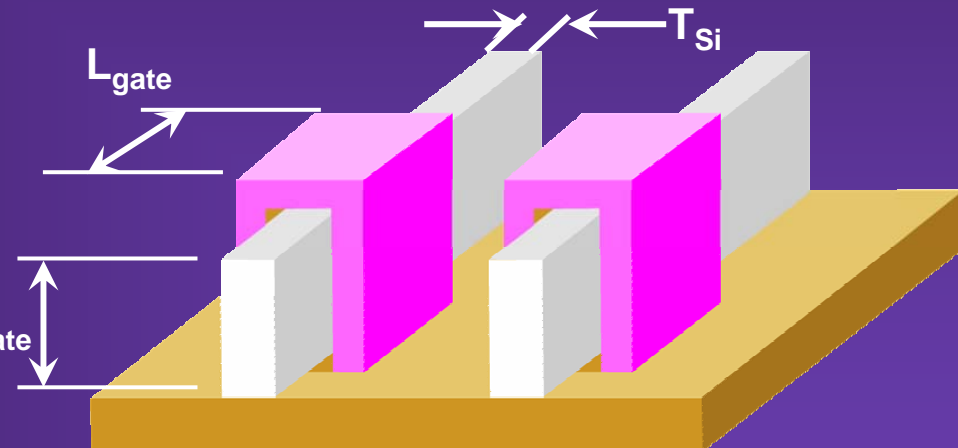
The Power-Saving Spectrum



Devices for High Speed / Low Power



$$\text{Fin height} = 1/2 W_{\text{gate}}$$



$$I \propto 2 \text{ Fin height} / L_{\text{gate}} \times N_{\text{fin}}$$

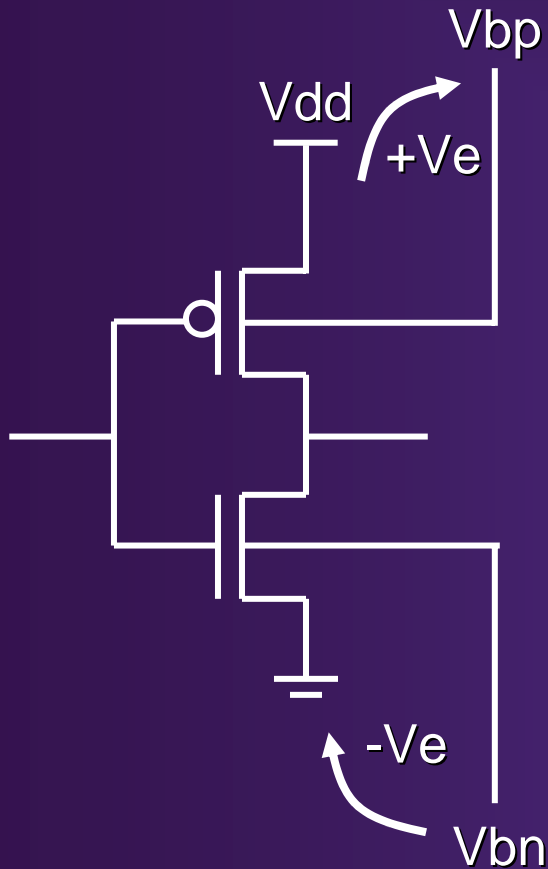
Vertical dimension not litho limited

Leakage Power Circuit Techniques

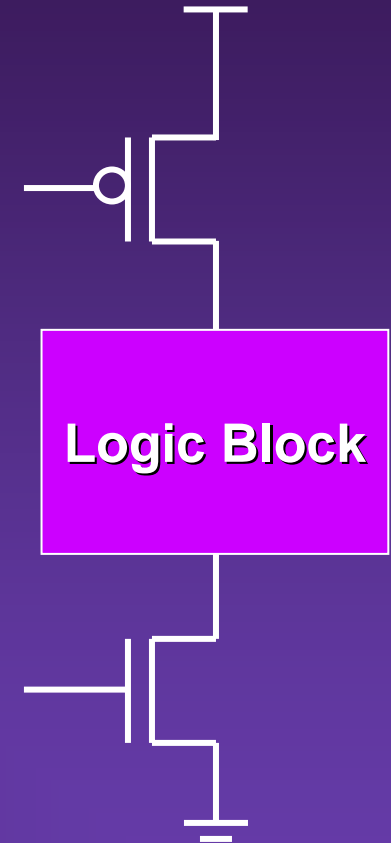
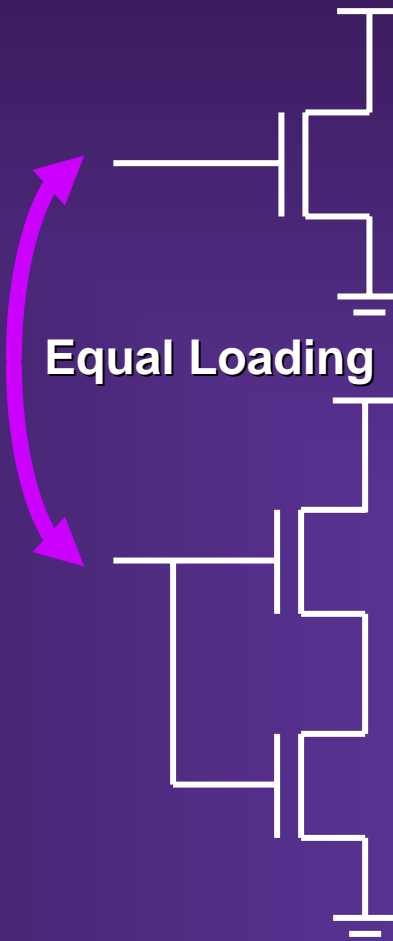
Body Bias

Stacked Transistors

Sleep Transistor

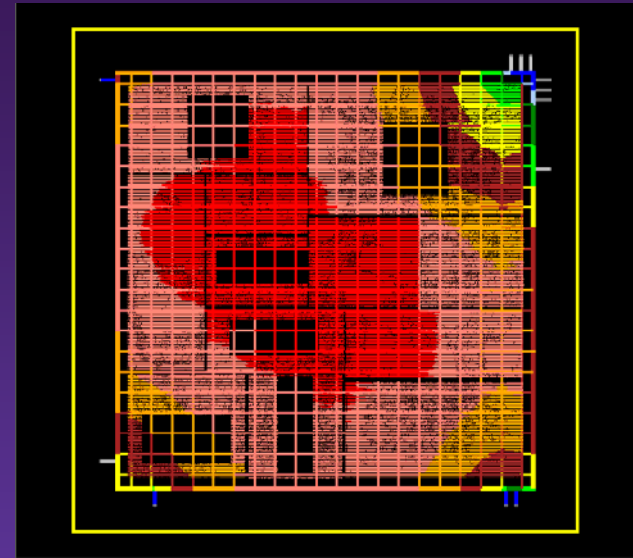
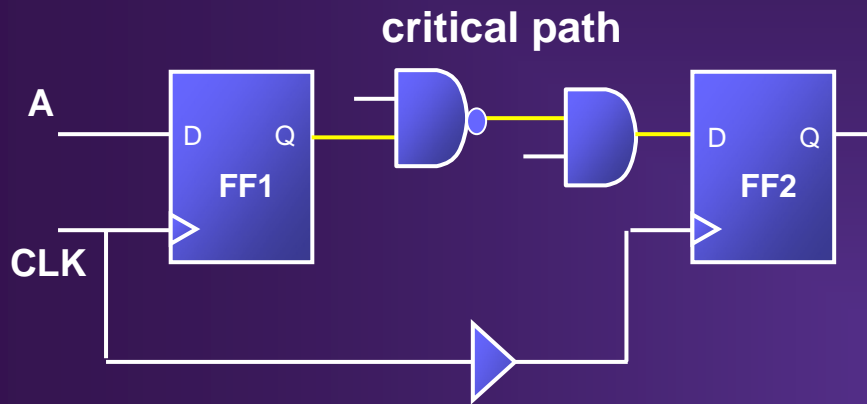


2-10X Reduction



2-1000X Reduction

Timing vs. Power

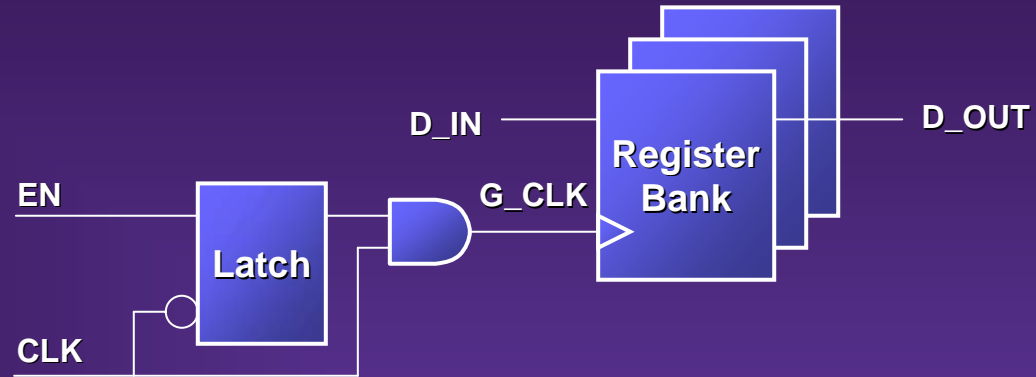


Trading

- Old days: delay for area
- Now: power for delay

RTL Clock-gating

```
always @ (posedge CLK)
  if (EN)
    D_OUT = D_IN
```



Design	Size	Power Savings
RISC Core	220K	52%
LCD Display Block	400K	35%
Adaptive Computing	1200K	61%

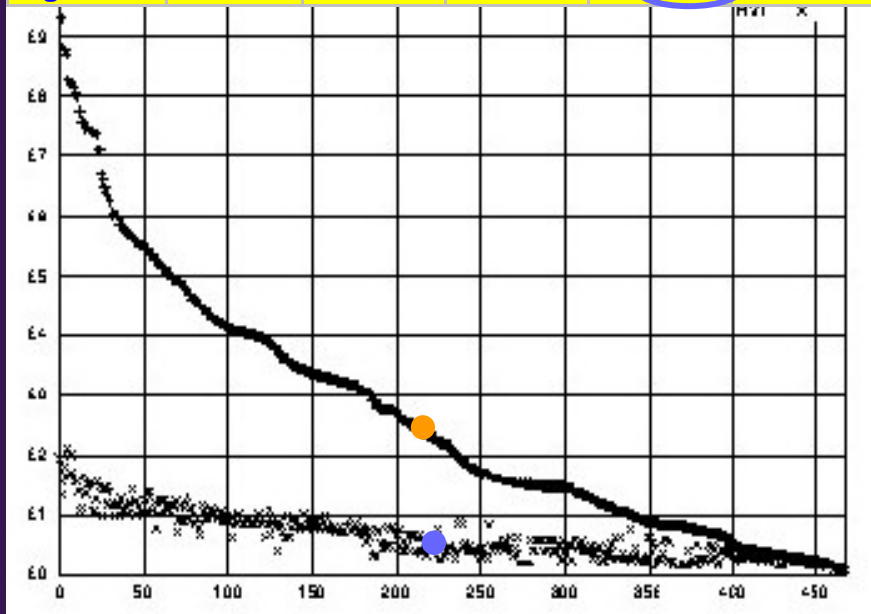
Dual- V_{th}

Decreasing Threshold Voltage Increases Leakage!

180nm Dual- V_{th}

Leakage Power [0 to 1] nW

	Vdd (V)	Delay (ps)	Leakage Power		
	Vdd (V)	Delay (ps)	Min (nW)	Aver (nW)	Max (nW)
Low V_{th} +	1.8	28	0.011	0.263	0.955
High V_{th} x	1.8	36	0.007	0.068	0.280

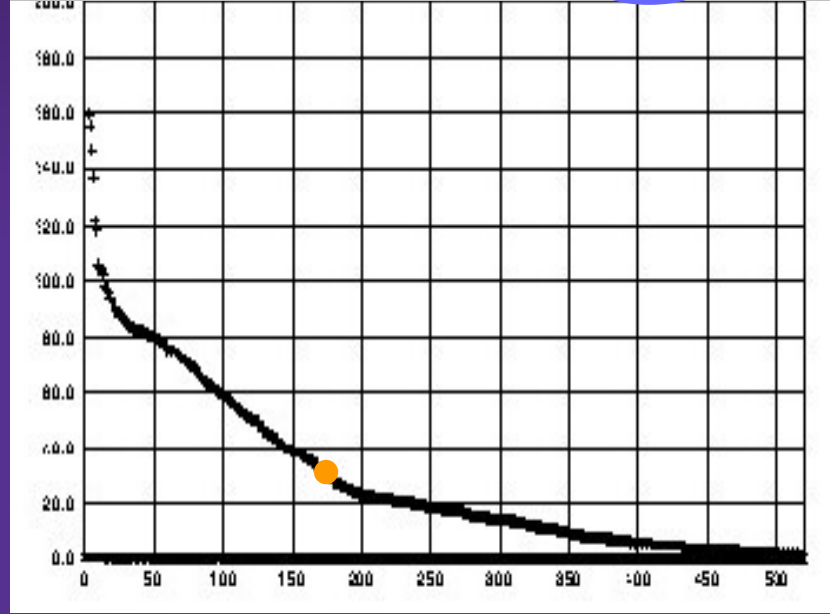


180nm Standard Cell Library

130nm Dual- V_{th}

Leakage Power [0 to 240] nW

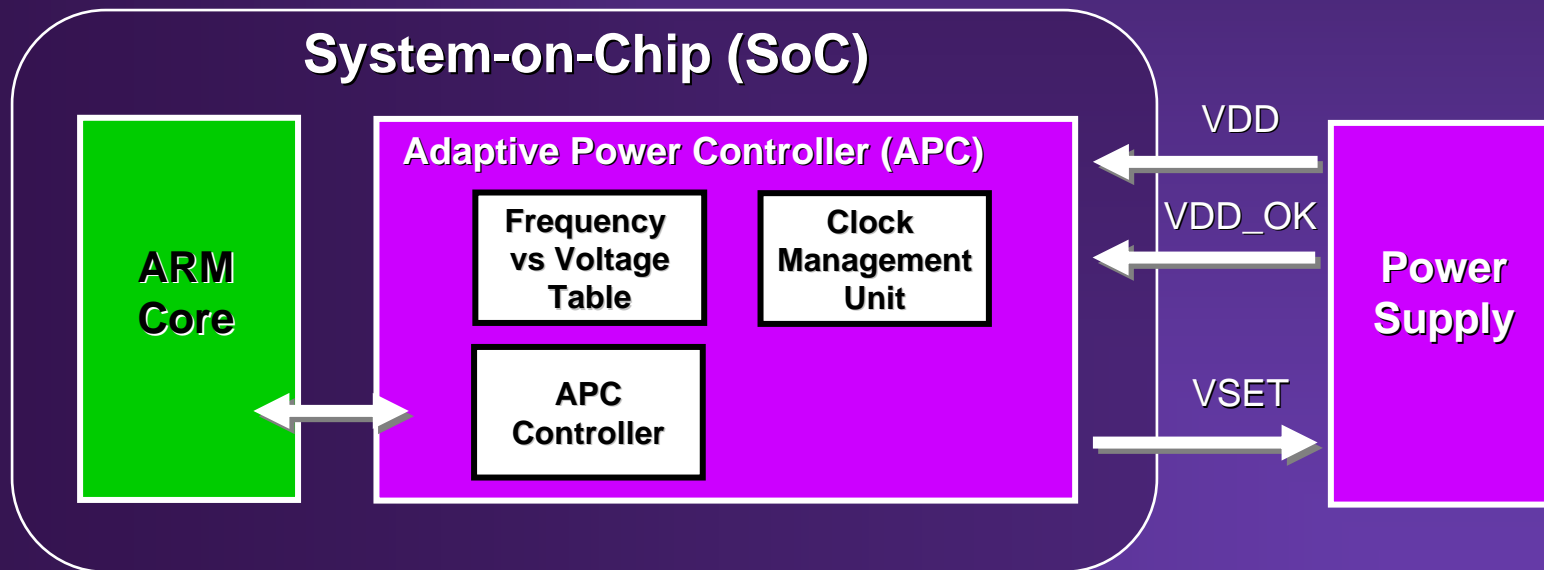
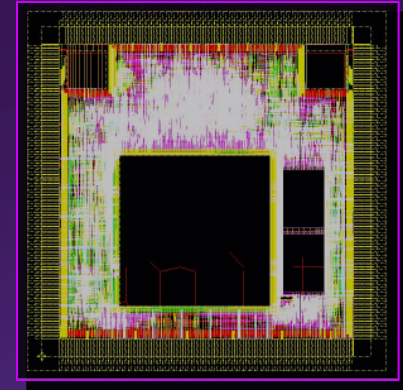
	Vdd (V)	Delay (ps)	Leakage Power		
	Vdd (V)	Delay (ps)	Min (nW)	Aver (nW)	Max (nW)
Low V_{th} +	1.2	10	1.135	30.779	233.395
High V_{th} x	1.2	16	0.002	0.043	0.580



130nm Standard Cell Library

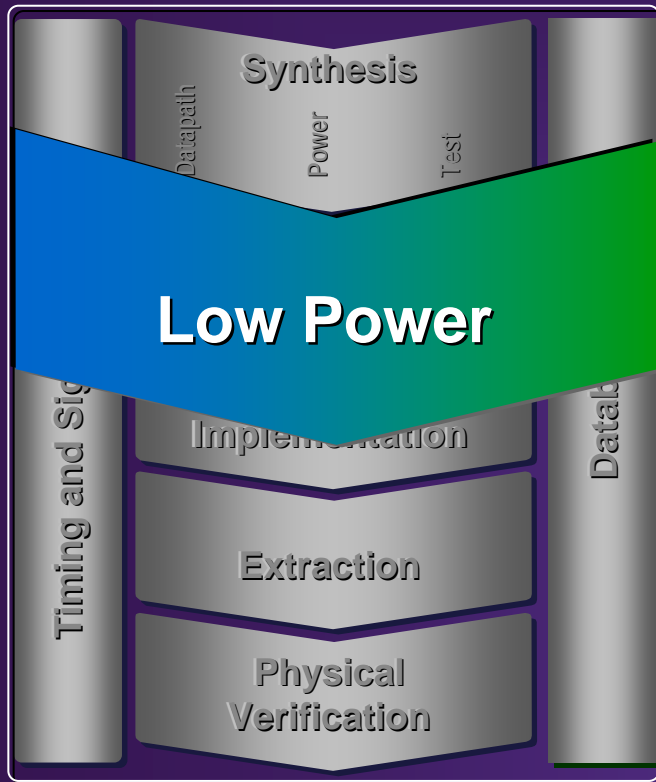
DVS Implementation

ARM926-DVS
Taped-out April '03



VDD_OK indicates when it is safe to update the clock

Future Trends



- Power density is doubling at every technology node
- Leakage power contribution increasing
- Power is tackled by technology, standards (GSM, OS), software, digital and analog hardware and tools
- Emerging trends include multi- V_{th} , multi- V_{dd} , dynamic and adaptive voltage scaling
- Power sign-off a must

Summary



Smaller, Cheaper

- DFM, Mixed Signal, Test, **etc**

Increasing Design Cost

- IP, **SLD**, structured ASIC, **etc.**

Faster

- Timing closure, SI, Statistical Timing, **etc.**

Less Power

- **Process**, **circuits**, **architecture**, **SW**, Energy efficient design

Design

SYNOPSYS®



> *Your Design Partner*

SYNOPSYS®